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Coordinator Contact	Régis Hamelin BLUMORPHO 38 rue Mermoz, 75008 Paris E-mail: hamelin@blumorpho.com Tel: +33 678 13 24 31

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Author(s)	Radia Lahlou, Régis Hamelin
Reviewer(s)	Akbarjon Usarov

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aCCcess Project

The **aCCcess project**, launched in **March 2025**, supports the implementation of the **EU Chips Act** by establishing and coordinating the **European Network of Chips Competence Centres (ENCCC)**. The project aims to strengthen Europe's semiconductor ecosystem through structured collaboration, shared infrastructure, and strategic networking between **Chips Competence Centres (CCCs)**, **Chips Pilot Lines (PLs)**, and the **Design Platform (DP)**.

Over a four-year period, aCCcess will ensure synergies between these key Chips Joint Undertaking (Chips JU) initiatives by facilitating harmonised practices, shared technology offers, and a unified approach to innovation and skills development. The ENCCC will be structured around five thematic focus groups: **Operations and Best Practices**, **Outreach and Events**, **Common Technology Offers**, **Training and Skills Development**, and **Finance**.

Key actions include:

- Development of a **shared online marketplace** featuring CCC service catalogues, AI-supported matchmaking, and simplified access to training and infrastructure.
- Organisation of **online and in-person events**, including an annual community meeting, to enhance cross-border collaboration.
- Promotion of **funding opportunities** through the **Chips Finance Lab**, investor matchmaking, and a dedicated **start-up pitching event**.
- Establishment of a **Chips Think Tank** and regular **webinars** to facilitate knowledge exchange, highlight best practices, and support cluster development.

Expected Impacts:

- Improved accessibility and visibility of CCCs, PLs, and the DP for European businesses, particularly SMEs and start-ups.
- Strengthened innovation capacity through early access to advanced semiconductor technologies.
- Enhanced coordination and expertise sharing across Europe's semiconductor value chain.
- Greater funding access and innovation financing opportunities.

aCCcess serves as the integrative framework to unlock the full potential of Europe's semiconductor initiatives, positioning the continent as a global leader in chip design, development, and production.

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1. INTRODUCTION

European semiconductor start-ups and SMEs play a strategic role in strengthening Europe's position across the global semiconductor value chain, notably in chip design, advanced materials, manufacturing equipment and specialised technologies. However, these companies face significant challenges in accessing adequate financing. Compared to software-driven ventures, hardware innovation requires substantially higher upfront investment, longer development cycles and complex industrialisation processes, resulting in increased investment risk and slower capital deployment. As a consequence, many promising European semiconductor companies encounter structural difficulties in securing early-stage and growth financing.

Chips Competence Centres (CCCs) have a key mission in supporting innovation ecosystems and facilitating access to venture capital for emerging companies. While CCCs are strongly embedded in regional innovation landscapes and provide proximity support to start-ups, each centre individually faces limitations in reaching the critical mass of investment opportunities required to attract investors on a recurring basis and to maintain long-term engagement with venture capital communities. This fragmentation reduces visibility for European companies and limits the creation of sustained investment dynamics at European level.

The aCCcess project addresses this gap by bringing together the European Network of Chips Competence Centres (ENCCC) and leveraging Blumorpho's expertise and established connections with venture capital and corporate investors. By pooling high-potential companies identified across multiple Competence Centres, aCCcess enables the aggregation of deal flow and the construction of a structured and attractive portfolio of semiconductor investment opportunities. This collective approach strengthens Europe's capacity to present investment-ready companies at a scale aligned with investor expectations.

Within this context, the Chips Venture Forum (CVF) was established as the operational instrument to implement this ambition. The CVF is organised as a recurring initiative designed to identify, evaluate and showcase start-ups and scale-ups emerging from the ENCCC ecosystem. Functioning both as a start-up competition and an investment matchmaking platform, it creates structured interactions between companies and a diversified community of venture capital, corporate and institutional investors.

The Chips Venture Forum pursues the following operational goals:

- **Facilitating access to finance** by structuring sustained engagement between European semiconductor start-ups and a broad range of financial actors, including VC, CVC, corporate investors and debt providers.
- **Supporting scaling of SMEs** via tailored pitching opportunities, network mobilisation and visibility across investment communities by improving access to private and public financing, strengthening strategic partnership.
- **Strengthening ecosystem coordination** by bringing together actors from the CCC network, EIC ecosystems, Chips JU partners and the private sector to create synergies and shared investment interest.

- **Increasing the visibility and attractiveness of European deal flow** in the semiconductor domain, thereby contributing to broader strategic objectives on industrial competitiveness and technological sovereignty. Also, strengthening collaboration between industry stakeholders, investors and authorities to accelerate scale-up of the high-potential companies in European semiconductor ecosystem.

These Objectives are shared with the European Innovation Council and for this first edition, the DGCNECT and EIC decided to join forces with the Network of Competence Centers to support the European Ecosystem of Start-ups.

The Forum's target audience includes semiconductor start-ups and scale-ups across categories (fabless, materials, design, equipment), venture capital and corporate strategic investors, ecosystem intermediaries, and European innovation stakeholders. Its design, combining digital pre-selection, evaluation and an annual physical event, ensures continuity of engagement and reinforces Europe's structured approach to bridging the gap between innovation capacity and capital deployment.

This deliverable D6.3 presents the mapping of companies identified through the Chips Venture Forum process, highlighting investment opportunities emerging from the ENCCC network and contributing to a more visible, coordinated and investment-ready European semiconductor ecosystem.

2. Preparation Phase

2.1. Startup Application and Selection Process

2.1.1. Eligibility Criteria

In agreement with the Chips JU and EIC, the eligibility criteria were defined. Companies applying to the Chips Venture Forum need to be:

- **Active within the semiconductor value chain:** Companies must operate within the semiconductor value chain, from materials to chip packaging, including equipment and EDA. All segments of the semiconductor value chain are eligible. System integrators without specific semiconductor-related intellectual property (IP) are not considered eligible.
- **Connected to a Competence Centre or supported by the EIC:** The core objective of the Chips Venture Forum is to identify start-ups emerging from the respective ecosystems of the Chips Competence Centres (CCCs). Within the framework of the partnership with the European Innovation Council (EIC), companies currently supported by an EIC grant are also eligible to participate in the CVF.
- **Established in Europe:** As aCCcess is funded under the Digital Europe Programme, the programme's eligibility rules apply for all companies applying via their CCC. For candidates applying under the EIC framework, Horizon Europe eligibility criteria apply.

2.1.2. Open Call and Application process

The Chips Venture Forum (CVF) is structured as a multi-stage competition (*Figure 1*) designed to identify and prepare high-potential companies for engagement with investors. The process begins with an open application phase during which candidate companies submit their

proposals. Applications are then evaluated through an online jury selection process. As part of this evaluation, each selected company participates in three individual online one-to-one meetings with venture capital firms, with matchmaking between start-ups and investors organised by Blumorpho. Following the online assessment phase, a consensus meeting is held to consolidate jury feedback and finalise the selection of the top 18 companies, which are awarded the opportunity to pitch on stage. The process culminates in a final in-person event featuring a face-to-face pitching competition. All participating companies are invited to attend the event, enabling broader networking opportunities and direct interaction with venture capital firms and ecosystem stakeholders.

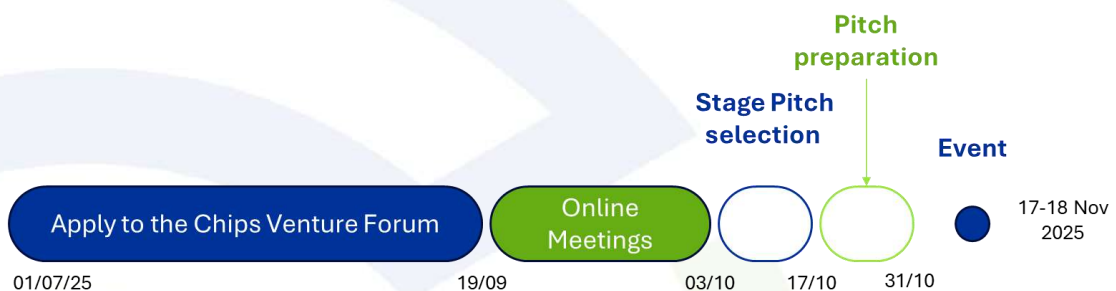


Figure 1: process and timing of the CVF 2025 edition

2.2. Recruitment Channels and Traceability

2.2.1. Recruitment Channels

In order to reach a critical mass of companies in the portfolio, our objective was to reach 50 applications for the competition. At the launch of the Chips Venture Forum, only 50% of the competence centers were in operation, so we have opened the applications beyond the EIC and CCC portfolios. Selected companies originated from multiple complementary channels, including:

- **EIC beneficiaries,**
- **Companies connected to the Competence Centre (CCC) network,**
- **aCCcess associated partners**
- **Blumorpho's SME and investment ecosystem database.**

This diversified sourcing approach ensured that the Forum attracted both companies already active within EU innovation frameworks and newcomers from the broader semiconductor ecosystem.

All participating companies entered the process under identical conditions and requirements. Participation in the digital sessions and the overall selection process was free of charge for all eligible European semiconductor companies. *Figure 2* represents applications by sourcing channel.

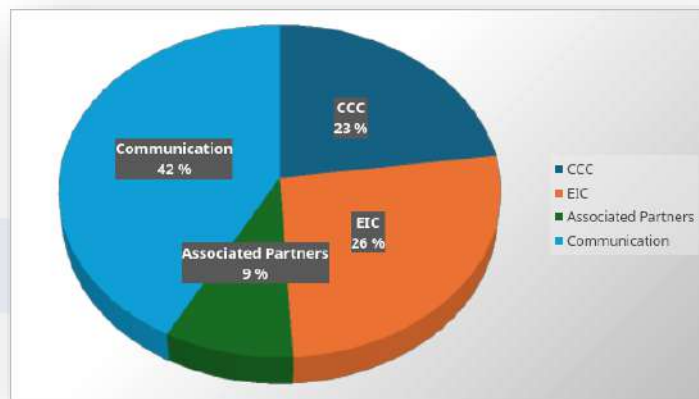


Figure 2: Breakdown of application per sourcing channel

2.2.2. Traceability Mechanism

To ensure transparency and enable structured reporting, a **traceability code field** was integrated into the application form.

Key characteristics of this mechanism were:

- The code appeared as an optional field in the online application form.
- Codes were distributed by ecosystem intermediaries, including Competence Centres, EIC-related actors and partners, to companies within their networks.
- The code was **not mandatory** for application.
- The code did **not provide any preferential treatment or competitive advantage**.
- It was used **exclusively for statistical and reporting purposes**, allowing identification of recruitment channels and ecosystem mobilisation.

This system ensured traceability without introducing discrimination or financial barriers. All eligible startups were admitted to the digital jury phase regardless of code usage.

2.2.3. Outreach Actions

The recruitment phase was supported by structured communication and direct outreach actions.

Key elements included:

- **4 targeted email campaigns** sent to a curated database of around (800 contacts),
- Direct mobilisation of CCC,

- Communication also relayed through **Silicon Saxony**, aCCcess communication manager,
- Promotion via the official LinkedIn accounts of **aCCcess** and **Blumorpho**.

2.3. Webinars and Ecosystem Engagement

2.3.1. Webinar Series Overview

As part of the preparation phase of the Chips Venture Forum 2025, aCCcess initiated the Chips Think Tank Webinar series organised between **July and February**, with a total of **three webinars**, each lasting approximately **60 minutes**.

These sessions contributed to:

- Promoting the Chips Venture Forum call,
- Preparing the ecosystem for participation with investors interviews and analysis,
- Positioning aCCcess as a platform for thought leadership in the European semiconductor domain,

Each webinar was organised in a panel and Q&A format and hosted via GoToWebinar. *Figure 3* shows aCCces YouTube channel and video recording from Chips Think Tank webinars.

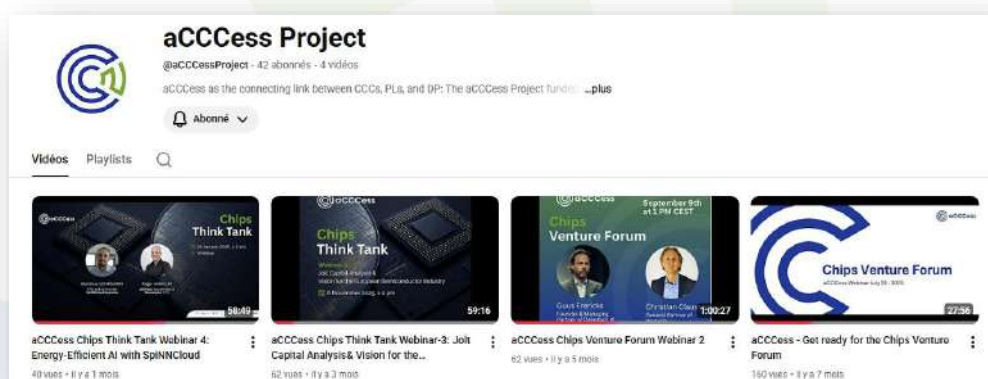


Figure 3: Chips Think Tank webinar series available from the aCCcess Youtube Channel

1. **Energy-Efficient AI: The Coming Breakthrough in Compute Acceleration**
– Matthias Lohrman, Co-Founder & CTO, SpiNNcloud Systems
2. **Jolt Capital Analysis & Vision for the European Semiconductor Industry**
– Jean Schmitt, President and Managing Partner, Jolt Capital
3. **What is the Chips Venture Forum?**
– Régis Hamelin, CTO of Blumorpho and Coordinator of aCCcess
– Radia Lahlou, Innovation Manager, Blumorpho

4. What Deep Tech Investors Look for in Semiconductor Start-ups?

- Christian Claussen, General Partner, Ventech
- Guus Frericks, Founder and Managing Partner, DeepTechXL

2.3.2. Website Visibility

The Chips Venture Forum (CVF) was announced on the aCCcess website, and a dedicated webpage was created on the Blumorpho website to centralise information related to the initiative: <https://www.blumorpho.com/chips-venture-forum/>.

The competition process is implemented as a turnkey activity supported by infrastructure readily available through the Blumorpho platform. Application submissions are collected through dedicated online forms, while the interfaces used for jury evaluation sessions are hosted within the non-public area of the Blumorpho website. The webpage serves as the main reference point for applications, programme information and event details. Web traffic analytics will be consolidated and reported separately where available.

3. Eligibility Screening

3.1. Geographic distribution

The call for applications for the Chips Venture Forum 2025 was open from 1st of July to 19th of September. Out of the 81 applications received:

- **23 applications were deemed ineligible**
- **58 companies were retained**, representing a **72 % selection rate**
- Applications originated from **17 European countries** (see *Figure 4*)

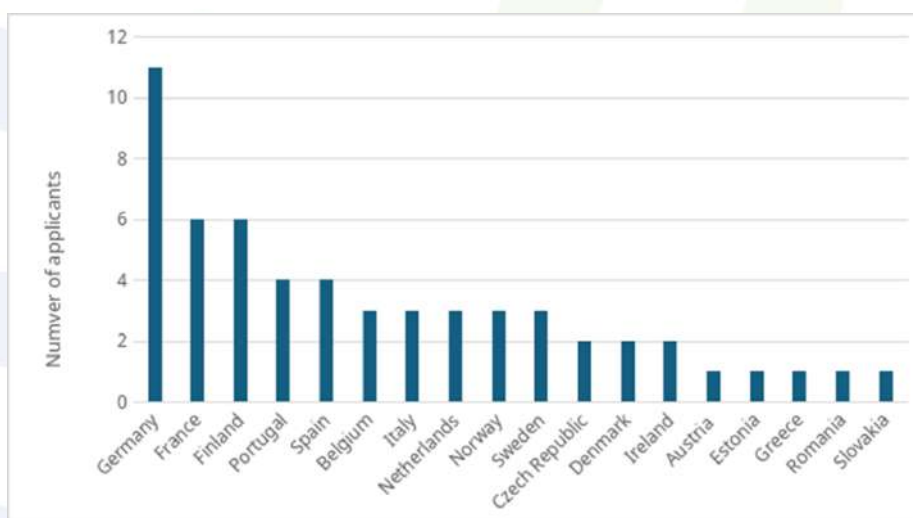


Figure 4: Number of applicants per country

The main reasons for non-fulfillment of eligibility requirements:

- Companies operating outside the semiconductor scope,
- Non-eligible countries (including applications from China, Turkey and the United States)

The 58 selected companies covered a broad range of maturity stages, including pre-seed, seed and later-stage scale-ups. No minimum Technology Readiness Level (TRL) threshold was imposed in order to ensure inclusiveness across innovation phases.

3.2. Sectoral Distribution

Applicants self-declared their technological positioning during the application process (multiple choices were possible). The distribution across categories included: AI/ML Hardware, Photonics, MEMS & Sensors, Mainstream semiconductor technologies, Equipment, Test, Materials, RF & mmWave, Power Electronics, Packaging, Quantum, EDA & Design Automation.

The strongest representations were observed in **AI/ML Hardware, Photonics which clearly reflects the current market traction of AI**. It is followed by MEMS & Sensors which is a specific strength of Europe. **Figure 5 graphically represents abovementioned statistics, so one can see that AI/ML Hardware was selected 13 times, following by Photonics which was chosen 12 times.**

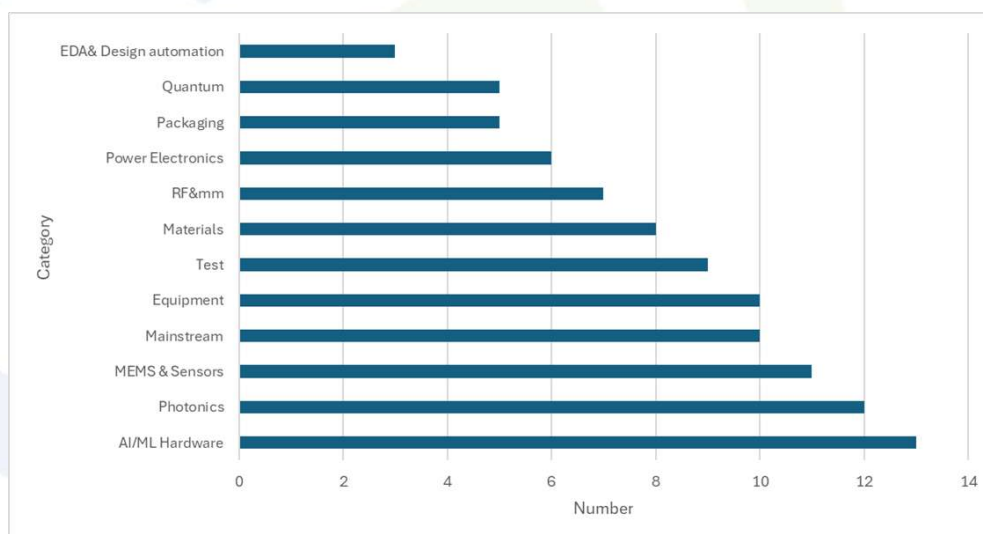


Figure 5: Field of Technology and applications

3.3. Selection Methodology

The selection process was structured in three sequential phases: (1) screening, (2) online jury, (3) consensus meeting

Initial screening conducted by Blumorpho, based on eligibility criteria. During this qualification phase, matchmaking between start-ups and Investors participating to the jury was performed. Criteria like business sector, business model and investment stage were the main criteria at this stage.

Participation of all eligible companies (58) in digital jury sessions, ensuring equal opportunity and conditions for evaluation. The jury sessions were conducted online in one-on-one meetings between start-ups and investors, consisting of a 5-minute pitch followed by a 5-minute Q&A session. Investors were given access to the application materials in advance. Each company could meet with up to three investors. The jury subsequently scored their level of interest in each company

The digital jury phase took place between 7 October and 31 October, spanning approximately four weeks. During this period, a total of 57 startups were evaluated through 144 online sessions, each consisting of an individual pitch meeting between startups and investors. One of the selected companies did not show-up to the planned meetings which explains the loss of 1 company among the eligible ones.

Jury consensus: Following the digital evaluation phase, a consensus meeting was organised to review and validate the outcomes of the selection process. The meeting brought together venture capital jury members, representatives from Blumorpho, the European Commission, and the European Innovation Council (EIC).

The scoring process produced a ranking of the evaluated companies, which was collectively discussed during the meeting by all investors participating in the jury. Lasting approximately two hours, the session focused on reviewing the consolidated evaluation results, confirming the final selection, and ensuring alignment among all stakeholders involved. This process ultimately led to the selection of 18 companies invited to pitch at the in-person Chips Venture Forum event.

This step strengthened the transparency of the process, enabled multi-actor validation, and ensured institutional alignment within the overall selection procedure.

4. Jury Recruitment

A total of **31 jury members** were mobilised for the digital evaluation phase of the Chips Venture Forum 2025.

The jury composition reflected strong financial expertise:

- **27 Venture Capital investors**
- **5 Corporate representatives**

This composition ensured a robust investment-driven evaluation while integrating strategic industrial perspectives.

Jury members were selected based on:

- Proven expertise in the semiconductor sector,
- Active involvement in deeptech investment,
- Portfolio exposure to semiconductor or hardware start-ups,
- Demonstrated understanding of the European semiconductor ecosystem.

The predominance of investment actors ensured alignment with the core objective of facilitating access to finance for semiconductor SMEs.

5. Chips Venture Forum 2025 – Physical Event

5.1. Location and Strategic Positioning

The physical edition of the Chips Venture Forum 2025 took place in Munich, at Messe München, on 17 and 18 November, in strategic proximity to SEMICON Europe.

The Forum gathered a total of **131 participants**, representing start-ups, investors, corporates, Competence Centres and institutional stakeholders from across Europe.

Organising the event in Munich, alongside SEMICON, provided direct access to the industrial and investment ecosystem present at Europe's leading semiconductor trade fair. This co-location enhanced visibility, facilitated the participation of international investors already attending SEMICON, and strengthened the positioning of the Chips Venture Forum within the broader European semiconductor value chain.

5.2. Pre-Event Networking Dinner

A networking dinner was organised on the evening preceding the main event.

All key participants, including investors, speakers, start-up and institutional representatives, were invited. The dinner created an informal setting for early-stage relationship building, facilitating deeper exchanges ahead of the official programme.

This format enabled strategic networking and strengthened investor–entrepreneur interactions prior to the formal pitching sessions. This preparatory interaction contributed to a more focused and productive engagement during the event itself.

5.3. Programme Structure and Content

The Chips Venture Forum 2025 physical event was structured as a one-day high-level programme combining policy, industry and financial perspectives.

The programme included:

- 2 panel discussions,
- 1 keynote session,
- 18 start-up pitches,
- A total of 14 speakers

The keynote session, titled *“Europe’s Path to Semiconductor Leadership: The Key Role of Competence Centers”*, emphasised the strategic role of Competence Centres within the European Chips Act framework. The talk was given by Pierre Chastanet, Head of Unit Microelectronics and Photonics Industry, European Commission.

The two panels addressed the questions of the European Market for European Start-ups and the financial value chain available in Europe to support its start-up ecosystem. Speakers represented a balanced mix of European institutions, venture capital, corporates and ecosystem actors.

- *“How to Make Europe an End-Users Market and a Strong Value Chain for European Chips?”*
Moderated by Régis Hamelin, Coordinator of aCCcess and CTO of Blumorpho. Invited speakers were:
 - Timo Tenhovuori, Head of Semiconductor Strategy, Nokia
 - José Miguel Pascual, Head of Innovation Centers, Indra
 - Katharina Westrich, Global VP of Semiconductors and Electronics, Siemens
 - Sarah Luppino, Principal, M Ventures
 - Elly Zwartkruis, Programme Manager ChipsNL, Brainport Development
- *“A Strong Financial Value Chain for the European Semiconductor Industry – Chips Act, VC, PE, IPO and Capital Markets”* Moderated by Géraldine Andrieux, President of Blumorpho.
 - Marco Ceccarelli, Programme Officer, DG CONNECT, European Commission
 - Isabel Obieta, Programme Manager for Sustainable Semiconductors, EIC
 - Thomas Ferré, Senior Investor, European Investment Bank (EIB)
 - Christian Claussen, General Partner, Ventech
 - Dr. Christian Reitberger, Founding Partner, Matterwave Ventures
 - Dr. Helmut Gassel, Partner & Co-Founder, Sillian Partners

The programme ensured strong institutional presence while maintaining a clear investment and industry focus. Figure 6 shows panellists invited to the discussion.



Figure 6 : Panel sessions

Left: Panel 1- from left to right: Timo Tenhovuori , Elly Zwartkruis, Sarah Luppino

Right: Panel 2 – from left to right: Christian Reitberger, Marco Ceccarelli, Helmut Gassel, Christian Claussen, Thomas Ferré

5.4. One-to-One Meetings On-Site

In addition to the pitching sessions, structured one-to-one meetings were organised throughout the event.

A total of 127 meetings were conducted on-site, each lasting approximately 15 minutes.

The matchmaking process prioritised:

- Connections not previously established during the digital jury phase,
- Meetings based on declared investor interest and sectoral alignment.

This hybrid approach (digital pre-evaluation followed by physical targeted meetings) maximised the quality and relevance of investor–startup interactions.

5.5. Participant Profile

The 131 participants represented a diverse cross-section of the European semiconductor ecosystem:

- 67 participants from start-ups
- 37 investors and corporates
- 28 representatives from Competence Centres and institutions

This balanced composition ensured a dynamic environment combining capital providers, technology innovators and policy actors. From figure 7 one can see the examples of the one on one meetings.



Figure 7: One on one meetings between Start-ups and Venture Capital

5.6. Award Ceremony and Recognition

The event concluded with the announcement of three awards, determined by investor voting during the Forum. The final award decisions were based on votes cast by investors present in the room, with the companies receiving the highest number of votes in each category being selected.

The Winner of the Chips Venture Forum 2025 was Vertical Compute, represented by Sylvain Dubois.

***Vertical Compute** is pioneering a new generation of in-memory computing architectures integrating logic and MRAM technologies to overcome traditional data-processing bottlenecks. This approach enables highly energy-efficient AI and edge computing applications, contributing to scalable and sustainable intelligent systems.*

A jury “Coup de Cœur” in the category Sustainable Semiconductors was awarded to **FaradaIC Sensors, represented by Ryan Guterman**. The company develops miniaturised electrochemical gas sensors integrated on microchips, enabling ultra-compact, low-power detection solutions for IoT, medical and industrial applications.

A second “Coup de Cœur”, recognising Potential in Energy-Efficient Devices, was awarded to **SpiNNcloud, represented by Matthias Lohrmann**. SpiNNcloud is developing brain-inspired AI inference infrastructure designed to deliver ultra-energy-efficient and scalable computing performance.

These recognitions aimed to highlight promising European semiconductor companies and to reinforce their visibility within the investment and industrial ecosystem.



Figure 8: Chips Venture Forum Awardees FaradAIC (left) , Vertical Compute (center), SpiNNcloud (right)

6. Post-Event Assessment and Impact Analysis

A satisfaction survey was conducted shortly after the event, between 24 November and 22 December 2025, gathering **39 responses** from a balanced mix of investors, corporates, innovative companies and Competence Centres. (see Annex 2)

Overall results confirm a **high level of satisfaction and strong ecosystem relevance**.

More than **70% of respondents rated the event 8/10 or above**, with an average score above 8/10

In addition, **92% expressed their intention to participate in the 2026 edition**, and nearly all respondents indicated they would recommend the Chips Venture Forum to their peers

This demonstrates strong loyalty and recognition of the Forum as a valuable ecosystem platform.

Beyond satisfaction, the results highlight **concrete business impact**:

- The Forum generated **112 new qualified connections** among participants
- More than half of respondents already foresee **concrete deal opportunities in the coming months**, including investment rounds, due diligence processes and strategic partnerships.
- Around **80% of companies reported having built valuable new connections**, primarily with investors and corporates

The evaluation also confirms the robustness of the preparation process:

- **97% positive ratings for the application process**
- **91% positive ratings for the digital jury phase**, confirming its relevance as an efficient screening and alignment mechanism
- **92% positive ratings for programme and content**, demonstrating strong alignment with ecosystem needs
- Networking and environment were among the highest-rated dimensions (95% positive), confirming that the Forum successfully enabled high-value interactions

Participants particularly highlighted:

- The quality and relevance of investor interactions,
- The efficiency of the Forum as a deal-sourcing platform,

- The value of bringing together investors, corporates, startups and institutions under the strategic umbrella of the European Chips Act.

While one-to-one meetings were identified as an area for further optimisation (mainly due to occasional no-shows), feedback confirms that improvements are incremental rather than structural.

In summary, the Chips Venture Forum 2025 demonstrated:

- Strong ecosystem mobilisation,
- High satisfaction across stakeholder categories,
- Tangible pipeline generation,
- Alignment with the objectives of aCCcess and the European Chips Act.

Detailed survey results and full quantitative analysis are provided in Annex 1.

Follow-up surveys will be conducted 3 months and 6 months after the event to monitor the impact of the CVF on the actual fundraising of companies.

7. Conclusion and next steps

The first edition of the Chips Venture Forum generated strong interest from both the VC and start-up communities, confirming the need for a coordinated European effort to support fundraising in the semiconductor sector. The partnership with the EIC and DG-CNCT enabled the pooling of resources to scout a high-quality portfolio and bring together investors with a clear investment thesis in this field.

For this first edition, the objective was to establish the brand and create a strong foundation for future editions. For upcoming editions, aCCcess aims to:

- Strengthen scouting through the CCC network: approximately one quarter of the participating companies originated from CCCs. In 2026, the CCC network will be fully operational, and we expect this number to increase significantly.
- Renew the partnership with EIC and DG-CNCT: 50% of the companies selected to pitch on stage have received EIC support, demonstrating the effectiveness of this instrument. As a high-quality portfolio is essential to the attractiveness of the initiative, maintaining this partnership is key.
- Integrate additional partnerships: EuroCDP, designed as an acceleration programme for start-ups, represents a strong potential partner to be included in future editions.

At present, the start-up portfolio is also attracting strong interest from Pilot Lines, which can identify potential users of their resources. In the future, as Pilot Lines transition into a service-delivery mode, they may also become an important sourcing channel for the CVF.

Over the next three years of aCCcess, we aim to establish the Chips Venture Forum as the annual flagship meeting dedicated to semiconductor start-up investment in Europe.

ANNEX – A – Start-up Portfolio of the Chips Venture Forum 2025

AGATE SENSORS

Category: Mainstream Silicon Technologies, Photonics



AGATE SENSORS



Startup



Finland

www.agatesensors.com

AGATE Sensors, a deep-tech company pioneering a novel pixel-based, ultra-miniaturised, software-defined broadband spectral CMOS-based sensor platform, delivering nanometre-accurate spectral reconstruction in a solid-state format, enabling both measurement and imaging applications. This disruptive innovation is 10,000x smaller and up to 100x more cost-effective than traditional spectrometers.

Solution description:

New, patented, mass-producible broadband light sensor, operating from 400-950nm. Software-defined, providing lab-grade spectral accuracy. Breaking trade-offs between spectral resolution, spatial resolution, signal-to-noise, and tailor algorithms to specific use cases. Solid-state & robust. All incident light is used. High framerate, high spectral & spatial resolution, hyperspectral video possible.

Problem solved:

Current sensors struggle to identify enemies at long ranges and in low-light conditions. Complex terrains and camouflage hinder rapid and accurate targeting. Lack of mass-deployable software-defined spectral sensors is limiting the deployment of battle edge AI systems.

Differentiation:

Our technology is based on semiconductor physics discoveries done at Aalto University, now patented and commercialized by AGATE Sensors Oy. The founding team of AGATE Sensors combines unique capabilities in R&D management, commercialization, business development, strategy planning, and execution.

Business model:

Fabless B2B, selling chipsets and companion software to our device manufacturing customers.

Targeted markets:

Smart wearables "hyperspectral PPG", imaging and sensors applications within defence and security systems.

Unique Selling Proposition (USP) of your solution:

We are offering a global first software-defined light measurement and imaging sensor platform breaking traditional performance trade-offs and allowing for a continuous capability improvement by rolling software updates. – 10 000 X smaller – 1000 X cheaper than traditional filter-based solutions.

Expected Collaboration:

Connections to OEM customers, Foundry contacts Investors

AIML TECHNOLOGY

Category: AI/ML Hardware



Startup



Germany

<https://youtu.be/l6fgtBYtou4>

AiML Technology is a semiconductor startup developing a proprietary number-system-based AI chip tailored for edge inference. Its goal is to enable ultra-low-power, high-efficiency, and private on-device AI for IoT, wearables, smart home devices, and robotics.

Problem solved:

AiML tackles edge AI's critical problems: high energy use, cloud dependence, and privacy risks. These drive short battery life, high OPEX/CAPEX, and poor scalability – directly hurting OEM margins and consumer trust in next-generation devices.

Solution description:

AiML Technology brings high-efficiency, on-device AI to the edge — delivering up to 50× efficiency gains, 5– 10× longer battery life, and full privacy by default. OEMs gain performance and autonomy without cloud overheads, unlocking scalable, smarter consumer electronics with lower lifetime cost.

Differentiation:

AiML differentiates through a patented number system delivering 50× efficiency vs. FP32, a validated FPGA prototype, and strong IP portfolio.

Expected Collaboration:

AiML seeks OEM, semiconductor, and investor partnerships to scale edge AI silicon. We are raising €10M seed funding to produce first silicon, drive pilots, and prepare for Series A expansion.

ALCYON PHOTONICS

Category: Photonics



Startup



Germany

<https://youtu.be/l6fgtBYtou4>

Alcyon Photonics designs the next-generation photonic integrated circuits (PICs). We develop fabrication- independent IP libraries—branded as PIP Cores®—that allow our customers to accelerate the development of high-performance, scalable photonic chips for datacom, telecom, AI infrastructure, and sensing applications.

Problem solved:

The development of custom photonic chips is slow, expensive, and fragmented. Companies face long cycles, high costs, and limited access to innovation. The industry urgently needs reliable, modular, and foundry-compatible photonic blocks to meet performance, cost, and time-to-market requirements.

Differentiation:

Proprietary IP (PIP Cores®) imeta-material approach, which we have uniquely industrialized.

Technical expertise: deep know-how in PIC design Foundry integration: Strong relationships and validated IP across top-tier foundries. Toolchain interoperability with key EDA. Agility to design support.

Unique Selling Proposition (USP) of your solution:

We deliver high-performance, fabrication-ready photonic IP (PIP Cores®) that reduce design complexity, speed up time-to-market, and ensure foundry compatibility. Our modular IP accelerates integration, cuts development costs, and boosts scalability for customers.

Solution description:

Alcyon's PIP Cores® are pre-validated, foundry-compatible design blocks are compatible with leading PDKs and foundries (Tower Semiconductor, GlobalFoundries, etc.), significantly reducing the time, risk, and cost of new product development. We also support designs integrated with industry-standard EDA tools (Ansys, Synopsys, Luceda), enabling smooth simulation and layout.

Targeted markets:

We target high-performance PICs for datacom, telecom, AI, defense, and quantum markets. Our focus is on tier-1 customers in the US and EU, addressing needs in scalable, fabrication-ready integrated photonics.

Business model:

We generate revenue by licensing our PIP Cores® IP blocks, offering design services, and engaging in co-development projects. Our model supports recurring income through licensing while enabling tailored solutions and revenue from custom designs.

Expected Collaboration:

Strategic investment to accelerate early commercialization. We're raising €5–10M.

ALLOS Semiconductors

Category: Materials & Substrates



Scaleup



Germany

www.allos-semiconductors.com

We develop and sell Galliumnitride-on Silicon (GaN-on-Si) epiwafer for micro-LED applications. Our global customer base is using this material to manufacture next-generation displays (e.g. Augmented Reality) and light machines for optical interconnect (OI) in AI chips. We operate fabless (with a foundry in TW), are 11+ years in business, generate >1 m. in sales, are debt-free, and c/f positive.

Problem solved:

Futuristic micro-LED-based display prototypes have been around for many years, but poor yield still prevents mass manufacturing. ALLOS' customers overcome this by manufacturing in silicon wafer fabs. Equally OI (i.e. next generation interposer for AI chips) requires manufacturing in silicon fabs.

Differentiation:

We have an proprietary GaN-on-Si growth technology protected by ~100 global patents.

Unique Selling Proposition (USP) of your solution:

Our epiwafer material is admitted to silicon fabs. This enables our customers to use 200 or 300 mm Si foundries or inhouse fabs with much better yield, and potential for cost cutting and scaling up instead of continuing to use comparatively "dirty" and low-resolution 100 or 150 mm LED fabs

Expected Collaboration:

Although being already profitable, we will need 7 to 8-digit funding once our customers go into volume production to maintain our global leader position.

Solution description:

To use silicon fabs requires silicon-compatible wafer material. ALLOS is the only company which can offer 200 mm and 300 mm GaN-on-Si for LED applications. To manufacture cost effective at small volume AND to enable future very fast scaling up of manufacturing we manage manufacturing at a foundry in Taiwan and several other global supply chain partners.

Targeted markets:

North America and East Asia. Both micro-LED displays and micro-LED based optical interconnect.

Business model:

We have > 1 m. EUR revenue p.a., ~65% from wafer sold, rest project revenue and government R&D grants. We are profitable and c/f positive. We are a key enabler for technologies with the potential to disrupt the display and interposer chip industries

ALTRATECH LTD

Category: MainstreamSiliconTechnologies, MEMS&Sensors, [Other]



Scaleup



Ireland

www.altratech.com

Altratech's team of 20 scientists and engineers has developed a completely new multi-analyte molecular diagnostic method, for detecting and quantifying infectious viruses, DNA, RNA, Antibodies and Antigens. Based on PNA probes and a low-cost CMOS semiconductor detector chip, this is the first to deliver concurrent serology and nucleic acid detection in a single In-Vitro-Diagnostic (IVD) device.

Problem solved:

Our PNA probes capture viruses directly from blood or saliva, eliminating centrifuges and pipettes. Our digital CMOS capacitive sensing eliminates the bulky and expensive laser optical detection of PCR and other diagnostic methods. The result is our easy-to-use portable diagnostic, with the simplicity and low-cost of a lateral-flow test, but with PCR accuracy (250 copies/mL Limit of Detection).

Differentiation:

There are no MEMS, nanotubes, nanorods, electrochemistry, or other gold or magnetite special layers, i.e. no special processing or manufacturing/scale-up limitations. The technology is protected by 8 patent families, with 40 patents granted worldwide & 12 pending, all assigned to Altratech Ltd.

Unique Selling Proposition (USP) of your solution:

We offer ease of use by non-clinical/untrained people, and rapid triage of ill patients in clinics, to differentiate bacterial from viral infections (enabling immediate treatment instead of hospitalisation). Our Low-test cost (& €199 reader unit) means no CAPEX needed (vs >€10k for competitors).

Solution description:

The WHO 'REASSURED' criteria has long called for an accurate robust non-laboratory portable viral RNA diagnostic (at a single-digit cost-per-test) to address the ongoing unmet need of early diagnosis of HIV, HCV, TB viruses. Our semiconductor-CMOS based portable diagnostic solves this unmet need. Equally OI requires manufacturing in silicon fabs.

Targeted markets:

The TAM in molecular diagnostics is \$48B. The Point-of-Care SAM is \$9B which we target, initially the \$2B Infectious Diseases segment (HIV, HCV, TB, Cancer, respiratory). CAGR is 18% in eHealth and telemedicine, strong emerging applications for us.

Business model:

Up-front Licensing Fees & a 10% royalty on partner end-market sales – similar to Eiken (Japan) business model for LAMP diagnostics, which commands ~5% (~\$2B) of the Dx market. Also direct sales to Gates Foundation and NGO's, via the WHO pre-qual route

Expected Collaboration:

Ideally a Life-science/semiconductor €2M to €4M investor and to join our €8M B-round (to match €8M from EIB). The €16M total will fund trials, scale-up & market launch.

ALUVIA PHOTONICS

Category: Photonics



A L U V I A



Startup



Netherlands

<https://aluviaphotonics.com/>

Aluvia delivers the first Al_2O_3 PIC platform with ultra-low loss, broad transparency, high power handling, and scalable on-chip amplification. We remove the bulk, cost, and integration limits of current amplifiers, giving customers compact, high-performance, and scalable photonic solutions.

Problem solved:

Current optical amplifiers trade performance for scalability: DFAs are bulky, SOAs lack power and add noise. Quantum, telecom, datacom, and LiDAR need scalable on-chip amplification, while AR/VR and sensing need low-loss visible guidance, but current platforms fail to guide blue light.

Differentiation:

Aluvia is a PIC technology platform provider uniquely based on Al_2O_3 . We hold 3 key patents on material structure, dopants, and device structures, and our know-how in Al_2O_3 deposition and on-chip amplification enables performance and wavelength coverage no other platform can match.

Unique Selling Proposition (USP) of your solution:

Aluvia delivers the first Al_2O_3 PIC platform with ultra-low loss, broad transparency, high power handling, and scalable on-chip amplification. We remove the bulk, cost, and integration limits of current amplifiers, giving customers compact, high-performance, and scalable photonic solutions.

Solution description:

Al_2O_3 PIC platform combining ultra-low loss, broad transparency, high power handling, and scalable on-chip amplification. It overcomes DFA bulkiness and SOA limits, while enabling efficient blue-light guidance for AR/VR and sensing.

Targeted markets:

We target amplifiers for quantum, telecom, datacom, and LiDAR, plus AR/VR and sensing. Focus regions are Europe, North America, Taiwan, Japan, and Singapore, leading in photonics adoption and growth for our scalable Al_2O_3 PIC platform.

Business model:

We generate revenue through MPW runs, dedicated wafer and die sales, packaged devices, plus NRE for customization and design support. We partner with Tier-1 foundries for scalable manufacturing, enabling recurring revenue from prototype to volume.

Expected Collaboration:

We seek strategic investors to support scaling with Tier-1 foundries and customers. We aim to raise €10M in a Series A to fund industrialization, team growth, and market expansion.

AMSIMCEL SRL

Category: EDA&DesignAutomation



Startup



Romania

www.hyperpv.com

AMSIMCEL is developing HyperPV, a Physical Verification framework that accelerates the entire process from silicon to interposer, heterogeneous integration, and advanced packaging. Powered by the first GPU-based engines (DRC, LVS, ERC, 3D rules), it enables semiconductor firms to speed verification and boost production.

Problem solved:

Complexity of 3D-ICs, including heterogeneous chiplet designs that can amount to 1T+ transistors and other structures, needs to be thoroughly verified before manufacturing to avoid unwanted delays, save costs, and meet the expanded demand.

Differentiation:

HyperPV introduces disruptive EDA features: a proprietary computational geometry library for massive parallelization, ultra-fast engines, high scalability, and the rst PV SaaS framework enabling seamless deployment on-premise or on commercial GPU clouds.

Unique Selling Proposition (USP) of your solution:

HyperPV offers: 1) Speed—GPU acceleration reduces Physical Verification runtime by up to 20x; 2) Lower costs—cutting ownership expenses by 30%+; 3) Scalability—its proprietary computational geometry library enables massive parallelization on modern processors.

Solution description:

AMSIMCEL solved this issue by bringing the unprecedented General Purpose Graphic Processor Units (GPGPU's) acceleration capabilities into the next generation of IC design for Physical Design Verification (PV) of 3D-IC and future systems within the Electronic Design Automation (EDA) market.

Targeted markets:

We target the global Electronic Design Automation (EDA) software market, valued at €19.22B in 2025 is projected to reach €28.85B by 2030, growing at a CAGR of 8.46% during the period 2025- 2030.

Business model:

Revenue model is based on selling licenses on a period of time (from 1 up to 3 years or pay-as - you-use). We position in the Electronic Design Automation ("EDA") market.

Expected Collaboration:

With growing traction among global semiconductor leaders and momentum from the AI revolution, Amsimcel is now launching a EUR 6M Series A to scale its breakthrough technology.

ARGO SEMICONDUCTORS SA

Category: RF & mmWave, AI/ML Hardware



Startup



Greece

www.argosemi.com

ArgoSemi leverages expertise in analog RF design and analog AI circuits to create disruptive 5G and 6G active antenna solutions, that enable cost-effective deployments of advanced cellular, TN and NTN infrastructure. At the forefront of analog AI circuit innovation, ArgoSemi addresses critical challenges in power efficiency and scalability, overcoming existing infrastructure limitations.

Problem solved:

The energy efficiency is the most wanted quality dictating the Total Cost of Ownership in every radio system, while the analog radio part is responsible for about 70% of the consumption. Yet, the analog subsystems are controlled with bulky, feedback-heavy architectures that add complexity and cost.

Differentiation:

-Proprietary Analog Neural Network AI technology -Deep understanding of all relative technical domains (RF integrated circuits, AI, antennas, communications) -Strong and growing patent portfolio -Team engaged in the development and sales of more than one billion IC parts; extensive market channels

Unique Selling Proposition (USP) of your solution:

a. Unique technology and solution with wide applicability b. Improve energy efficiency for radios requiring analog beamforming and therefore bridge the efficiency gap between TN and NTN. c. Enable lower SWaP (Size, Weight and Power) d. Enhance modularity and scalability e. Lower TCO

Solution description:

Argo uses analog AI chip to enable high efficiency radios, that are modular and compact, also addressing the problem of energy efficiency in hybrid beamforming systems. This is achieved by introducing an analog supervisor semiconductor IC to support the idealization of the Power Amplifier circuit, in place or as a complement of digital counterparts.

Targeted markets:

Our primary target is the Radio Access Network (RAN) market and particularly the semiconductor segment in 5G, 6G (TN and NTN). In the longer term, we will launch our analog controller in all markets that utilize the GaN amplifier technology.

Business model:

ArgoSemi follows the fabless semiconductor business model (revenues from sales of integrated circuits – Smart RFIC and stand-alone AI controller). Also, it sells reference Active Antenna Boards as a tool for promoting its silicon.

Expected Collaboration:

ArgoSemi aims a Series A round of €4.8M where up to €2.4M : co-funding the development of our silicon and to grow a sales network.

BANYAN.ECO

Category: EDA & Design Automation, [Other]



banyan.eco



Startup



France

<https://banyan.eco/>

Banyan.eco enables eco-design from wafer to system. The SaaS offering addresses key value chain nodes of IC manufacturing, PCB manufacture, System assembly and OEM. It includes :

1. Sector specific Cradle-to-grave Lifecycle Analysis modelling
2. AI agents for substance/chemical intelligence and regulatory compliance
3. AI models for resource optimization and supply chain resilience

Problem solved:

The complexity and specialization of the electronics supply chain and industrial processes and the difficulty and lack of standards in gathering data makes eco-design and supply chain resilience planning manual, expensive and unreliable – across IC, system design (OEM) and manufacture (EMS).

Differentiation:

- Understanding of the end-to-end electronics supply chain and industrial processes
- Experts in environmental modelling
- Agentic AI technology specific to electronics - Lead the IPC sustainability standard development
- RTO collaboration (under NDA) on semi-process modelling & data

Unique Selling Proposition (USP) of your solution:

The only solution that covers the entire electronics value chain and uses primary data, thanks to industry-specific models, standards, and automation. Customers save big (3 months to 3 min) when carrying out lifecycle assessments and gain competitiveness in eco-design and supply chain resilience.

Solution description:

Banyan.eco is a digital twin of the key manufacturing steps of the electronics supply chain – underpinned with validated, primary (manufacturer) data. Thus any part in the value chain can analyse the multi-tier inputs and environmental footprint of its products in minutes. Use of primary data ensures trust in competitiveness related decisions around eco-design and supply chain resilience.

Targeted markets:

Semi design and fab (Europe, Japan, US) EMS and PCB makers (Europe, US, China, SE Asia) Markets of automotive, healthcare, energy, building automation, prosumer (global) Consumer OEMs

Business model:

Subscription model, per product SKU

Expected Collaboration:

We aim to raise a seed round of 1M€ to accelerate the go2market for the customer target segments where we already have traction, and to fund the compute infrastructure for AI agents and fab modelling

CHIPMETRICS

Category: ProcessEquipment&ManufacturingTools



CHIPMETRICS



Scaleup



Germany

<https://chipmetrics.com/>

Chipmetrics develops unique MEMS-based test chips for advanced 3D metrology in semiconductors. Our products and services enable precise, inline-compatible thin-film analysis in complex structures, helping fabs, tool makers, and R&D centers improve process development, tool qualification, and quality assurance in next-generation chip manufacturing.

Problem solved:

In semiconductor manufacturing, precise thin-1m control in complex 3D structures is a bottleneck. Conventional metrology lacks accuracy and fab-compatibility, causing yield loss, higher costs, and delays for fabs, tool makers, and R&D centers.

Differentiation:

Chipmetrics stands out with proprietary MEMS-based HAR test chips, the only solution worldwide for precise, non-destructive thin-film analysis in complex 3D structures. Backed by ALD/CVD and MEMS expertise, IP, and a strong leadership team, we turn innovation into scalable customer value.

Unique Selling Proposition (USP) of your solution:

Chipmetrics offers the only MEMS-based HAR test chips for fast, precise, non-destructive thin-film analysis in 3D structures. Customers gain faster process development, reliable tool qualification, and inline monitoring, reducing yield loss, delays, and cost in chip production.

Solution description:

Chipmetrics delivers breakthrough metrology with MEMS test chips, pocket wafers, and services. Our solution enables fast, precise, non-destructive thin-1m analysis in 3D structures, fully fab-compatible. It supports accurate process control, tool qualification, and inline monitoring, reducing costs, accelerating development, and improving yield.

Targeted markets:

Chipmetrics targets semiconductor fabs, equipment makers, and R&D centers for precise 3D thin-film control. Applications include process development, tool qualification. Initial focus: Japan, South Korea, and the U.S., with Europe to follow.

Business model:

Chipmetrics follows a fabless model, selling standardized MEMS test chips & pocket wafers, plus custom solutions. We also provide measurement services, combining scalable product sales with recurring service revenue for growth and customer retention.

Expected Collaboration:

We plan a Series A or Bridge round, depending on 2026 traction. Target size is ~€10M (€5-15M).

CHIP NANOIMAGING AS

Category: Test & Instrumentation Equipment, Photonics



Startup



Norway

<https://www.chipnano.com/>

Chip Nanolmaging (CNI) is commercializing a photonic chip waveguide based wide field of view super resolution microscope (SRM) that allows high throughput and large data that redefines the limits of super resolution microscopy/nanoscopy with advanced photonic technology.

Problem solved:

Current SRM systems have a field of view (FOV) with images on the size of 10-50 μm^2 . This severely limits the throughput of the techniques since only parts of a cell, or up to 1-2 cells can be imaged simultaneously. CNI's chip based SRM increases image FOV & throughput 100 fold

Differentiation:

The photonic chip wave guide microscopy system is patented by the University in Tromsø and Chip Nanolmaging has the global exclusive license

Unique Selling Proposition (USP) of your solution:

For end users; CNI technology allows scientists to detect and quantify biological events and features that are otherwise not detectable or quantifiable. This can relate and be vital to the success of research into new treatments and therapies for serious health conditions.

Solution description:

SRM has become an enabling tool for biological discovery in a short time, but several challenges remain to be solved. Large FOV chip-based waveguide nanoscopy solves some of the problems and opens up new routes in diagnostics, where high throughput is needed for the detection of non-di use disease, or rare events, such as the early detection of diseases, such as cancer

Targeted markets:

Spatial omics, molecular diagnostics, pathology, and pharmaceutical research markets in NA, Europe and Asia Pacific.

Business model:

Revenues will be generated by sales to end users (direct and through distributors), license agreements, and component sales to other microscope OEM's.

Expected Collaboration:

The company is aiming to raise a Series A round of financing of at least 15 MEUR.

COMPTeK SOLUTIONS

Category: Materials & Substrates, Process Equipment & Manufacturing Tools



Startup



Finland

www.comptek-solutions.com

We provide passivation technology for III-V semiconductor devices. Our innovative surface treatment process effectively transforms the surface of III-V materials into a high-quality native crystalline oxide layer, minimizing surface defects. We help our customers achieve drastic improvement in performance and manufacturing yields of optoelectronics and power transistors.

Problem solved:

Oxidation is a common source of defects in compound semiconductor devices. These defects, are the root cause for poor device performance and reliability, as well as increasing manufacturing complexity. The oxide appears as an amorphous native oxide layer that the industry tries to remove

Differentiation:

We have 39 patents, covering process aspects, device architectures and equipment-related topics. We have a multiskilled team of 27 covering material physics, chemistry, thin film deposition and device characterization, making Comptek's know-how and expertise top-level

Unique Selling Proposition (USP) of your solution:

Depending on application, our USPs are different: For high power lasers, we offer the highest quality/ cost-of-ownership ratio available in the market, plus an additional benefit related to the stability of the samples treated with our process, so that the manufacturing flow becomes more flexible.

Solution description:

Our novel technology, eliminates ca.98% of surface state defects in III-V materials in a counterintuitive way. We performed oxidation in a very controlled environment, generating high quality crystalline native oxides. This results in higher performance of optoelectronic or power electronic chips.

Targeted markets:

At the moment we are focusing in : High power edge emitting lasers: for medical, military, communications, applications Power electronics and RF GaN based devices

Business model:

Technology transfer and licensing.

Expected Collaboration:

We are not actively raising, but we are exploring for potential investors for our B series.

CONTINIUM TECHNOLOGIES

Category: Mainstream Silicon Technologies, Test & Instrumentation Equipment,



Startup



Slovakia

www.comptek-solutions.com

Continium Technologies is a fabless chip design company that create proprietary designs of high-performance data converters for wireless and defense applications. We create chips that provide a solution to the data throughput limitation and performance-power-price tradeoff through our implementation of a unique chip design architecture called Continuous-Time Sigma-Delta (CTSD).

Problem solved:

Most Data Converters utilize Successive Approximation Register (SAR) (CTSD). SAR's next generation products are only developed using geometry scale-down not architecture innovation which will cannot meet future customer requirements and provides a price-performance dilemma.

Differentiation:

Our team has world level expertise and experience in CTSD chip technology, thus we design and produce the best CTSD chips that will shake up the data converter market. Our team designed 1st commercially available CTSD high performance data converter.

Unique Selling Proposition (USP) of your solution:

Alternative to SARs chip architecture problems. We provide the solution to the data throughput limitations and performance-power-price tradeoff, with compact and efficient chips; all while we support our customers with the integration of our chips.

Solution description:

We are designing an alternative to the SAR chip problem by focusing on CTSD architecture. By focusing on architectural innovation, we offer a product that will meet future customer requirements and solves the price-performance dilemma.

Targeted markets:

Targeting European and American markets, we will be focusing primarily on the wireless telecommunication infrastructure and radar integrator markets, but our chips can be applied in other applications.

Business model:

Currently, pre-revenue. We target companies within listed market segments, and create contracts within companies that use data converters in production. For each contract, chips will be mass produced to fulfill customer needs.

Expected Collaboration:

We are aiming to raise 2.5 million euros by the end of 2025 to continue operations and development, to match the IPCEI grant requirements. Stage: Seed

DIAMFAB

Category: Materials & Substrates, Power Electronics, Quantum Technologies



Startup



France

<https://diamfab.com>

Diamfab aims to revolutionize power electronics & quantum sensing using semiconductor diamond built on 30 years of R&D at CNRS and protected by 8 patents. Our main achievements include state of the art diamond devices (Schottky diodes, transistors, and capacitors) backed by industry leaders such as Schneider Electric, Thales, and General Electric through orders and collaborations.

Problem solved:

Today, about 10% of electricity is lost in every power conversion. Considering that 70% of electricity goes through at least one level of power electronics, it represents a global loss of 4 times the electricity consumption of France per year!

Solution description:

We exploit the unique properties of diamond as ultra-wide band gap semiconductor. Diamond allows to exceed key performance criteria of the power electronics industry compared to existing materials, allowing to divide losses by a factor of 3. DIAMFAB develops and produces synthetic diamond wafers with a unique control of electrical properties. Also, we design and build diamond-based devices.

Differentiation:

Our innovation unlocks diamond doping, a major bottleneck. We grow and dope at the same time to control the conductivity across all layers. So far the company owns 8 patents, mainly on component architectures, and several secret les on material manufacturing. The team is composed by 19 people.

Targeted markets:

Three steps approach as the technology level increases. 1) Niche market already accessible (radiation dosimeters and electrodes) – today 2) Killer apps (high temperature, defense and space power electronics) – 2030 3) Mass market – 2033

Unique Selling Proposition (USP) of your solution:

Diamfab technology has the potential to disrupt the industry, just as WBG technologies are doing now. Diamfab enables to take key advantage and take the lead in the future UWBG products, an advantage will be difficult to overcome later.

Business model:

Two complementary business models: – Diamond wafers combined with licences (component architectures and front-end process) IDM/foundries. – Power devices (diodes, transistors & capacitors) to specialized system integrators.

Expected Collaboration:

Diamfab has raised a seed round in March 2024 of 8,7M€. We are looking for a series A by mid 2026. Figures will be disclosed late 2025.

EYE4NIR

Category: MEMS & Sensors



EYE4NIR



Startup



Italy

www.eye4nir.com

EYE4NIR is a fabless semiconductor company developing scalable multi-band imaging for dual-use infrared vision. Its proprietary tech merges visible and SWIR into one compact sensor, cutting size, weight, and power while staying high-performance. Using standard microelectronics instead of costly materials, EYE4NIR enables affordable, mass-deployable imaging for vehicles, robotics, and industry.

Problem solved:

Compromised visibility is a major safety risk: 22% of crashes are weather-related, and nighttime fatalities are 3× higher. Current imaging tech often fail in low light, glare, or contrast, underscoring the urgent need for advanced imaging to improve driving safety.

Differentiation:

E4N's patented technology detects VIS-NIR and SWIR within the same pixel using a unique proprietary pixel design and read-out electronics. Built on Si and Ge, the imagers are produced with standard silicon foundry processes, delivering scalable, cost-efficient, and reliable advanced imaging.

Unique Selling Proposition (USP) of your solution:

Multi-band and hyperspectral detection within a single cost-effective image sensor. Our proprietary technology enables the integration of visible and SWIR (Short-Wave Infrared) imaging into a single, compact image sensor—reducing size, weight, and power (SWaP) while maintaining high performance.

Solution description:

EYE4NIR extends the imager's wavelength range into the SWIR, enabling vision through fog, smoke, and haze thanks to low scattering by di usive media, immunity to sunlight interference, enhanced low-light performance, and the ability to assess road conditions, particularly detecting thin ice sheets.

Targeted markets:

EYE4NIR targets the automotive market, boosting ADAS and DMS in low visibility. It also powers industrial automation for sorting, quality control, and machine vision, plus consumer electronics like under-display facial recognition and wearables.

Business model:

EYE4NIR is a fabless company that designs IP and partners with foundries for fabrication, then tests and integrates devices into modules for customers. Operating B2B, its revenue model combines device sales, and licensing in selected markets.

Expected Collaboration:

EYE4NIR is raising 6M€ (2/3 already covered), late-seed round. We are looking for a deeptech lead investor.

FARADAIC SENSORS

Category: Materials & Substrates, MEMS & Sensors

FaradaIC[®]



Scaleup



Germany

www.faradaic.io

FaradaIC has developed Faraday-Ox[®], the world's first oxygen gas sensor on a chip. Built with MECS- Technology[®] (Micro-Electro-Chemical-Systems), it delivers ultra-low power, high-accuracy O₂ sensing in a miniaturized, solid-state format. Ideal for food logistics, packaging, IoT, & med-tech, Faraday-Ox[®] is the first O₂ gas sensor from the semicon industry & is our first product.

Problem solved:

Compromised visibility is a major safety risk: 22% of crashes are weather-related, and nighttime fatalities are 3× higher. Current imaging tech often fail in low light, glare, or contrast, underscoring the urgent need for advanced imaging to improve driving safety.

Differentiation:

FaradaIC's core differentiation is our patented solid-state electrolyte, enabling the world's first chip-based electrochemical gas sensor. Developed in-house, this material makes true MEMS-compatible gas sensing possible. We control the full stack—from materials to end device.

Unique Selling Proposition (USP) of your solution:

Our chip-based O₂ sensors unlock entirely new applications, like smart packaging and compact wearables; previously impossible with traditional O₂ sensors. For legacy applications, we reduce total device cost by up to 60%, enabling scalable, low-cost integration for our clients.

Solution description:

Current O₂ gas sensors use liquid electrolytes that leak, degrade, & are incompatible with chip-based manufacturing. With our new chip designs and MEMS-compatible solid-state electrolytes, these sensors can be produced on chips at MEMS scale. This is enabled by breakthroughs in synthetic chemistry led by our CEO. Made in-house, our materials are integrated into chips during production.

Targeted markets:

We target high-volume markets needing cost-effective, miniaturized O₂ sensing: food freshness monitoring, smart packaging (beachhead markets), and other IoT/industrial applications. Our primary segments are Europe and North America.

Business model:

We generate revenue through unit sales of our chip-based O₂ sensors at volume, delivering high-margin components for scalable products. Long-term growth includes expanding our gas sensing portfolio (H₂, CO₂..).

Expected Collaboration:

We're raising a Series A (>€20M) to scale production and expand our sensor portfolio.

FLASH DIAGNOSTICS

Category: Mainstream Silicon Technologies, Test & Instrumentation



FLASH
DIAGNOSTICS



Startup



Portugal

www.flash-diagnostics.com

Flash – Rapid Diagnostics is a biotech company pioneering diagnostics-on-a-chip to tackle one of the world's most pressing health challenges: antimicrobial resistance (AMR). By blending nanotechnology, solid-state magnetic sensors, and microfluidics, Flash transforms conventional medical diagnostics into a fast, portable, and affordable chip-based platform.

Problem solved:

Antimicrobial resistance (AMR) is a growing global threat, causing 33,000 deaths annually in Europe alone. Hospitals lack rapid, affordable tools to detect resistant bacteria during patient admission. Delays in diagnosis lead to outbreaks, increased ICU stays, and avoidable deaths.

Differentiation:

Flash holds proprietary technology combining solid-state magnetic sensors, microfluidics, and AI, protected by international patents. Unlike optical systems, our chip-based detection is compact, cost-effective, and scalable.

Unique Selling Proposition (USP) of your solution:

Flash's Bactometer delivers rapid (<1h), strain-level detection of antibiotic-resistant bacteria at the point of care. It enables hospitals to isolate infected patients immediately, preventing outbreaks, reducing ICU costs, and improving patient outcomes.

Solution description:

Flash's Bactometer is a portable diagnostic device that detects antibiotic-resistant bacteria in under one hour, right at the point of care. Using magnetic chips instead of complex optics, it identifies pathogens quickly and affordably. This rapid screening helps hospitals isolate infected patients early, stopping the spread of superbugs.

Targeted markets:

Flash targets hospital-acquired infection (HAI) screening in ICUs, with a focus on detecting antibiotic-resistant bacteria. Initial markets include Southern and Western Europe, expanding to high-need regions globally.

Business model:

Flash will generate revenue through the sale of Bactometer devices and recurring revenue from disposable test cartridges. Our model targets hospitals and healthcare providers.

Expected Collaboration:

We seek strategic partnerships with hospitals and diagnostic companies for pilot deployments and clinical validation. We are aiming to raise €1.5M in a Seed round to achieve regulatory clearance.

FURNAQUANTUM

Category: MainstreamSiliconTechnologies,Materials&Substrates,Process



Startup



Finland

<https://furnaquantum.tech>

FurnaQuantum develops next-gen Silicon Carbide (SiC) ingots/wafers grown 2× faster (7 vs. 14 days), 4× cheaper, and 10× more precise. We enable scalable 6" wafer production, FAB-ready, with a roadmap to 8" and 12". The first furnace sale (€80K) proves traction. Our mission: unlock electrification of mobility, renewables, and industry. We are turning silicon carbide (SiC) to gold.

Problem solved:

FSiC wafer supply is the bottleneck for electric vehicles, renewable energy, and power electronics. Current furnaces are uncontrolled production, outdated, require >14 days per ingot, and deliver poor yields with high defect density. Results in expensive wafers, unmet demand, and stalled adoption.

Differentiation:

Competitors: Wolfspeed, STMicro, Coherent. Differentiation: Proprietary furnace design enabling faster, cheaper, defect-controlled growth. Validated by first furnace sale and first production-grade ingot. Positioned in Europe, where wide-bandgap is a strategic focus (vs. U.S. CMOS race).

Unique Selling Proposition (USP) of your solution:

FurnaQuantum delivers SiC wafers 2× faster, 4× cheaper, and 10× more precise in a fully controlled furnace environment. Our patented process cuts growth time (7 vs. 14 days), lowers defects (<1/cm²), and scales to 12". Customers gain reliable supply, higher yields, and lower cost per device.

Solution description:

FurnaQuantum's patented Quantum Phonon Aggregation IP furnaces use laser, ultrasonic, and electrical pulses to control thermodynamic nucleation. 50% faster growth cycles (7 vs. 14 days) Defect density <1/cm² (vs. >5 industry average) Lower energy operation (<1500°C) Scalability to 6", 8" and 12" wafers.

Targeted markets:

Targeting EVs, renewable energy, industrial automation, and aerospace/defense. SiC demand is soaring for inverters, chargers, and high-voltage systems. Market: €0.8B (2024) → €2.0B (2029), ~20% CAGR."

Business model:

Hybrid model: wafer sales to Tier-1 fabs, furnace sales to manufacturers (validated by €80k sale), and licensing to global partners. Target margins: 60–80%."

Expected Collaboration:

We are raising a €5M seed round (15% equity). Funds will scale 6" wafer production and deliver to pilot customers, and accelerate 8" furnace breakthrough toward global market leadership."

G2-ZERO

Category: Photonics, Quantum Technologies



Startup



Finland

g2-zero.com

g2-Zero is developing quantum light emitting devices and other photonic components based on semiconductors for applications in quantum communications, computing and sensing. Our goal is to make these devices accessible and cost-effective through an innovative approach to industrialisation which will accelerate the adoption of quantum technologies across different industries.

Problem solved:

The lack of commercially available high-brightness and high-purity quantum light sources represents a significant barrier in the commercial-scale deployments of quantum communication networks that are secure against quantum computers and which need high capacity, reliability and scalability.

Differentiation:

The design and functionality of g2-Zero's Plug&Play device were patented by the Spanish National Research Council (CSIC) with Benito Alén, co-founder of g2-Zero as principal inventor (EP3361516B1, US20200279972). In 2021, g2-Zero acquired a perpetual and exclusive license

Unique Selling Proposition (USP) of your solution:

We offer a cost-effective, easy-to-use solution for quantum research as well as for scaling quantum communication networks to commercial deployment. This will initially be of interest to quantum key distribution vendors and later to telco companies who will deploy quantum networks at a large-scale.

Solution description:

g2-Zero will sell a compact rack solution with up to 16 high-performance, Plug & Play quantum light sources, pre-coupled and ready to connect to quantum communication equipment for 24/7, unattended operation. The customer will choose how many devices they need initially and will add new channels via remote activation as demand increases thereby reducing initial installation costs.

Targeted markets:

g2-Zero will begin by targeting the R&D market, whose global investment level is currently \$55 bn and later the industrial quantum communications market which is estimated to be worth between \$11-15bn by 2035 and \$24-36bn by 2040.

Business model:

g2-Zero's will make revenue from the direct sales of its 2 product lines. We will release our MVP in Q1 2027 for the R&D market and later release our upgradeable and scalable agship product for quantum communications in Q4 2029.

Expected Collaboration:

Our current goal is to raise €6 M in seed funding resulting in our first sales of our MVP in Q1 of 2027 and sustaining us until 2029 for the release of our agship QKD product.

GREENBIT TECHNOLOGY

Category: Mainstream Silicon Technologies, Packaging & Assembly, Power

Greenbit Technology



Startup



Estonia

N/A

Building proprietary heat recovery solutions, capturing the excess heat from computing. Inhouse chip, electronics and mechanics R&D and manufacturing capability.

Problem solved:

High-performance computing generates waste heat while heating for homes & businesses is expensive. We turn this waste heat into a valuable resource. Our proprietary chip enables a modular hardware design that ends the costly 2-3 year ASIC obsolescence cycle, preventing waste and saving users money.

Differentiation:

Our in-house R&D team co-designs our proprietary chip, modular hardware, and network OS as a single system. This unique know-how solves hardware obsolescence and creates a network moat competitors can't replicate. Our proven track record of launching complex products de-risks execution.

Unique Selling Proposition (USP) of your solution:

Our USP is turning a major cost—heating—into a revenue-generating asset. Our permanent, upgradable hardware platform ends the costly 2-3 year obsolescence cycle, protecting our customers' investment and creating sustainable, long-term value.

Solution description:

We build computational heat recovery solutions. Our devices use the heat from computing resources (including our own proprietary chip) to provide efficient heating for homes & businesses, turning a waste product into a valuable resource. Our patented modular design allows for simple chip upgrades, which solves the problem of hardware obsolescence.

Targeted markets:

Our primary application is computational heating for the residential & commercial property sectors. We also target industrial applications in the energy sector. Initial geographic focus is Europe

Business model:

We will generate revenue from hardware sales and recurring income from regular upgrades and services. At scale, we will monetize our deployed infrastructure (i.e. grid operators)

Expected Collaboration:

We are raising a Seed Round for scaling manufacturing. We seek a strategic partner with expertise in scaling hardware manufacturing and semiconductor supply chains / network.

ILMSENS GMBH

Category: RF &mmWave



Scaleup



Germany

www.ilsens.com

At Imsens, our core competency is our proprietary UWB technology. Built on powerful, custom-designed ASICs for superior performance, it provides unprecedented, real-time insight into materials and processes. This technology is the foundation for our solutions in three key fields: Industrial Process Control, Non- Destructive Testing, and advanced Smart Sensor Systems.

Problem solved:

The core problem we solve is the critical lack of real-time information. We deliver in-depth (material) data in industrial manufacturing or industrial processes. We reduce significant uncertainties, risks and costly inefficiencies.

Differentiation:

Our fundamental differentiation is the symbiotic integration of our proprietary M-sequence UWB technology with our in-house, custom-designed semiconductors (ASICs). This creates a deep, multi-layered competitive advantage that is extremely difficult to replicate.

Unique Selling Proposition (USP) of your solution:

The USP is market-specific, but the basis is always the same: our technology delivers critical measurement data in a quality that has not been achieved before. This precise, real-time information directly from the process enables our customers to make informed decisions.

Solution description:

Impedance Spectroscopy for the real-time analysis and quality control of the composition of your process fluids and materials. High-Resolution Near-Field Radar for the non-destructive measurement of layer thicknesses, distances, internal structures, or smallest movements.

Targeted markets:

Primary markets: Chemical industry & process manufacturing, Construction and infrastructure sector, Mechanical and plant engineering (OEM), Security authorities / Public safety
Secondary markets: technology partnerships

Business model:

Product sales: Measurement systems and OEM sensors for industry (Minority atm).
Engineering services: Customised development solutions (Majority).
Licences: Software and data analysis algorithms (in the future).

Expected Collaboration:

The value of our technology increases with the integration of additional internal components, but this entails high NRE costs. We are seeking investors, strategic partners and experts for this task.

IMCHIP

Category: Materials & Substrates, AI/ML Hardware



Startup



Netherlands

www.imchip.ai

IMChip develops energy-efficient chips for future-proof computing, creating sustainable hardware for AI via developing its IP portfolio and process technologies that produce modular, scalable, and application-agnostic in-memory computing chiplets.

Problem solved:

Reliance on conventional architecture separating the memory and processor, and the rise in computation demands due to AI, has led to an unsustainable surge in energy demands. ChatGPT-4 generates 8.3 tonnes of CO₂ per day, while the training (inference) alone consumed around US\$63 million.

Differentiation:

IMChip's IP portfolio comprises the patent on which the core technology is based, along with upcoming patents on processes and circuit design with the crucial trade secrets for developing in-memory computing technologies. The R&D team comprises 4 PhDs in neuromorphic engineering.

Unique Selling Proposition (USP) of your solution:

Our main USP is the process technology capable of producing neuromorphic chips agnostic to a plethora of applications. The in-memory computing chips are integrable on the existing CMOS technology, will reduce power (energy) consumption, lower computation cost, and provide higher performance.

Solution description:

We develop neuromorphic hardware that co-locates memory and processor, utilising materials that mimic the functions of neurons and synapses in our brain. This low-power, low-latency, and high-performance computing hardware is specifically designed for AI tasks. This chiplet technology is CMOS-integratable and compatible with silicon processes, bringing the computation from the cloud to the edge.

Targeted markets:

We aim to target the edge AI, data centre and AI inference market in Europe and the US

Business model:

The 1st step towards revenue generation will be application-based IP licensing & partnerships for co-development and access to market segments. In the long term, we plan to work with bigger players in the data centre and AI accelerator market.

Expected Collaboration:

Raising €5M (seed round) to upscale technology, develop the MVP (including an IP portfolio), expand the tech and business teams, perform customer validation, and co-development partnerships.

INVIVO BIONICS

Category: Packaging&Assembly,ProcessEquipment&ManufacturingTools,



Startup



Norway

<https://www.invivo.io/>

Development and commercialization of medical devices based on in vivo pressure MEMS sensors for direct organ monitoring (humans & animals). The first application is continuous monitoring of the human urinary bladder, but the platform technology holds strong potential for other organs. Clinicians show high interest in its use for both diagnosis and treatment support.

Problem solved:

Lower Urinary Tract Symptoms (LUTS)

- including enlarged prostate, incontinence, and overactive bladder
- affect 1B people worldwide. PRESSURO is a diagnostic tool enabling accurate diagnosis and targeted treatment.

Differentiation:

Two patent families comprise 41 granted patents worldwide, secured under an exclusive license from SINTEF. The company carries know-how from SINTEF MiNaLab, transferred with two team members, and has advanced the solution to a CE-marked MDR class IIa device while developing multiple trade secrets.

Unique Selling Proposition (USP) of your solution:

Our main USP is the process technology capable of producing neuromorphic chips agnostic to a plethora of applications. The in-memory computing chips are integrable on the existing CMOS technology, will reduce power (energy) consumption, lower computation cost, and provide higher performance.

Solution description:

The core is a sub-1 mm MEMS pressure sensor for in vivo use, tethered to an external unit attached to the skin for storage and cloud transfer. In the cloud, data are analyzed. The wearable enables 24-hour bladder pressure monitoring during natural filling and voiding, while allowing undisturbed flow and providing entirely new insights into bladder function.

Targeted markets:

TAM (first product) is Europe, US, and Japan. In these geographical areas, 12M people remain unsuccessfully treated and constitutes our SAM. Our initial goal is a replacement of conventional urodynamics for LUTS (SWITCH).

Business model:

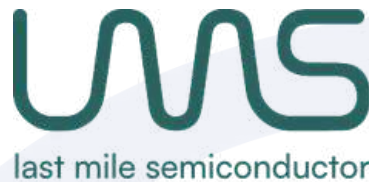
Provides a stronger basis for correct treatment, reducing repeated surgeries (e.g., 17–30% in prostate hyperplasia). Lowers patient no-shows from painful urodynamic testing. Enables parallel exams, easing bottlenecks and shortening waiting lists.

Expected Collaboration:

We aim to raise €15–20M in Series A (H1 2026) to scale production, accelerate marketing, sales, and distribution, run post-market superiority trials, and secure FDA approval following CE mark.

LAST MILE SEMICONDUCTOR

Category: Mainstream Silicon Technologies, RF & mmWave, AI/ML



Startup



Germany

www.lm-semi.com

Last Mile Semiconductor is a fabless semiconductor company in Dresden, Germany. We develop low-cost, long-range, ultra-low-power, and secure system-on-chips based on DECT NR+, a non-cellular 5G standard for Massive IoT. Our mission is to connect all sensor data in the world and make it usable for AI, analytics, and real-time applications.

Problem solved:

IoT needs long-range, ultra-low-power, and low-cost connectivity, but current options fall short. Cellular and LPWAN solutions drain batteries, require costly infrastructure, lack standardization, and pose security risks, limiting large-scale, affordable, and secure IoT adoption.

Differentiation:

LMS stands out through its deep know-how in wireless design and system-on-chip integration. Our patented DECT NR+ innovations deliver unmatched power efficiency, cost, and range. The team combines proven semiconductor expertise with early IP leadership, enabling a world-first NR+ SoC product.

Unique Selling Proposition (USP) of your solution:

LMS delivers the world's first DECT NR+ system-on-chip with 3× RF bandwidth, 4× data rate, half the cost and power of existing solutions. It features an integrated NPU, NVM, and secure element, enabling efficient, secure, and scalable IoT connectivity.

Solution description:

LMS solves the IoT connectivity gap with the world's first DECT NR+ system-on-chip. It delivers long-range, ultra-low-power, and cost-efficient wireless communication with 3× RF bandwidth, 4× data rate, half the cost and power. Integrated NPU, NVM, and secure element ensure secure, scalable Massive IoT without the need for costly cellular networks.

Targeted markets:

LMS targets the \$100B+ IoT market with ultra-low power, cost-optimized NR+ SoCs. Focus areas include smart metering, logistics, asset tracking, and industrial IoT, where long-range, secure, and scalable wireless is critical for growth.

Business model:

LMS sells standard ASICs based on DECT NR+, a low-power, long-range, non-cellular 5G standard for Massive IoT. Chips are offered under our brand or white-labeled to partners like Semtech. IP licensing provides additional royalty-based revenue.

Expected Collaboration:

Series A Collaboration with European Industry leaders.

LITHIUM LASERS

Category: Process Equipment & Manufacturing Tools



**LITHIUM
LASERS** Ultra pulses,
pure impact.



Startup



Italy

<https://lithiumlasers.com/>

We help customers optimize our patented GHz-burst femtosecond laser for real-world manufacturing. With unmatched control over burst shape and energy, our patented system boosts quality and throughput in semiconductors, packaging, and hard-to-machine materials like SiC and a variety of industrial glasses.

Problem solved:

Traditional SiC dicing with diamond saws is slow, imprecise, and requires frequent regrinding, causing downtime. TGV drilling in glass interposers often induces cracks due to thermal stress, limiting device reliability and lifespan in 3D chip packaging.

Differentiation:

We develop and produce our patented GHz-burst femtosecond laser. Our expert Application Lab supports customers with feasibility studies to demonstrate how to achieve crack- and debris-free SiC and glass processing with unmatched precision, speed, and reliability.

Unique Selling Proposition (USP) of your solution:

We optimize the settings of our patented GHz-burst femtosecond laser for semiconductor customers through our dedicated Application Lab and expert team, helping reduce costs and improve quality in their manufacturing processes.

Solution description:

Our patented GHz-burst femtosecond laser offers unique control over burst shape, pulse number, and energy distribution. Supported by a dedicated application lab and expert team, we deliver crack- and debris-free processing of SiC and glass with unmatched precision, speed, and reliability.

Targeted markets:

We target advanced packaging and semiconductors, focusing on SiC dicing, TGV drilling, and glass micromachining. Key markets are Europe, the U.S., and East Asia, where demand for high-precision laser processing is rapidly growing.

Business model:

We generate revenue by selling our patented GHz-burst femtosecond lasers, providing process studies to optimize laser performance for each customer's application, and offering specialized support for new materials and applications development.

Expected Collaboration:

5 Millions -Series A

LOGIICDEV GMBH

Category: Test & Instrumentation Equipment, Power Electronics, AI/ML



Startup



Austria

www.logiicdev.eu

Logiicdev (SME) is committed to enhancing global quality of life through advanced technology solutions. Our expertise supports digitization, AI-based edge solutions, and AI validation/testing. By combining innovation with practical application, we aim to accelerate the transition towards a renewable, sustainable, and technology-driven future.

Problem solved:

Using AI, GaN high-speed switching and patented tech, our battery solution cuts testing time by 20% and energy use by 24% across production, testing, and recycling—boosting throughput, reducing costs, and enabling more sustainable, scalable manufacturing.

Differentiation:

We differentiate through patented V.node tech in a scalable architecture with low SWaP-C (Size, Weight, Power and Costs). Our edge AI enables over-the-air upgrades across systems, while our expert team drives cloud-based AI/ML development for continuous optimization and adaptability.

Unique Selling Proposition (USP) of your solution:

V.node offers unified software and modular hardware for the full battery lifecycle formation, aging, testing, handling, and validation. It supports material-independent tech with edge-cloud connectivity and easy integration, ideal for R&D, DPSS, and recycling.

Solution description:

Patented Motherboard where user can connect different testing board, for formation, ultra aging, fast switching, EIS, Digital twin, abuse and Battery Fuel Gauges. This unified cloud connected solution can provide the AI model for safety, cost reduction, long life, predictive maintenance and recycling.

Targeted markets:

V.node is a holistic ML solution for sectors where battery reliability is vital. It serves EVs, ESS, and battery manufacturing/recycling with fast testing, predictive insights, and scalable performance to boost efficiency and reduce energy use.

Business model:

V.node generates revenue through AI edge model development, ML cloud subscriptions, hardware and software sales, and customizable test plugins for its GUI—offering scalable, recurring, and integration-friendly solutions across the battery lifecycle.

Expected Collaboration:

We seek strategic seed-stage investors for 4M€ to scale V.node's modular AI-driven battery tech. Collaboration in R&D and market access will accelerate growth and maximize impact.

MORESENSE SRL

Category: MEMS & Sensors



Startup



Italy

<https://www.moresense.tech/>

Moresense is a startup aiming at providing innovative and high-performance solutions for rapid monitoring of analytes of great concern (e.g. PFAS). The company innovatively integrates two different established chemical (MIP – Molecularly Imprinted Polymers) and engineering (optical and electronic devices) technological competencies to provide rapid, highly specific, and highly sensitive sensors.

Problem solved:

More and more PFAS are being listed as priority within EU and global regulations due to their health and environmental impact. Because of their rapid spread and hard removal, there is a huge demand for rapid and low-cost tools for their monitoring.

Differentiation:

We differentiate through patented V.node tech in a scalable architecture with low SWaP-C (Size, Weight, Power and Costs). Our edge AI enables over-the-air upgrades across systems, while our expert team drives cloud-based AI/ML development for continuous optimization and adaptability.

Unique Selling Proposition (USP) of your solution:

Moresense's sensors give the possibility to the customer to perform easily a rapid and efficient screening to determine the presence of PFAS without depending on third part laboratory. This solution allows the customer reducing drastically costs optimizing the monitoring process.

Solution description:

Moresense is developing specific chemical-electronic sensors able to measure PFAS in-situ without any pre-treatment or laboratory procedure. This approach responds to the increasingly stringent demands for continuous monitoring of the spread of hazardous substances and also allows for more effective emergency management.

Targeted markets:

Moresense targets the environmental sensor market, that is increasingly expanding, because there is a lack of sensors for specific chemical substances, such as PFAS.

Business model:

Moresense will generate revenues through royalties from a partnership agreement with an industrial commercial partner.

Expected Collaboration:

Moresense is working on a prototype version of the PFAS electronic sensor and is looking for investments of 1.000.000 €, including from technological/industrial partners.

N10GLED, LDA

Category: Photonics, Quantum Technologies



Startup



Portugal

www.entangled-space.com

N10gled aims to redefine cybersecurity as a quantum-resistant QKD constellation operator. Through the HEKATE satellite constellation and TAQS ground segment, we provide Quantum Keys as a Service, ensuring unbreakable encryption rooted in physics for secure global connectivity.

Problem solved:

Current cryptography is vulnerable to quantum computing. Fiber QKD is limited to ~400 km. N10gled solves this with HEKATE, a QKD satellite constellation, and TAQS ground stations, enabling global, physics-based encryption.

Differentiation:

N10gled differentiates with the agnostic TAQS platform, QKD-as-a-Service, and European sovereignty. We deliver low-cost, scalable keys for the commercial market, not only institutions. Backed by ESA collaboration and a fast startup mindset, we democratize access to quantum security.

Unique Selling Proposition (USP) of your solution:

N10gled offers Quantum Keys as a Service (QKaS), giving customers ultra-secure encryption without investing in or managing complex quantum hardware. With the HEKATE constellation and TAQS ground stations, we deliver scalable, global, quantum-resistant keys that cut cost, complexity, and risk.

Solution description:

N10gled delivers Quantum Keys as a Service through the HEKATE satellite constellation and TAQS ground stations. This integrated solution overcomes the distance limits of fiber QKD, enabling secure global distribution of quantum keys. Based on the laws of physics, these keys are inherently unbreakable, ensuring scalable, quantum-resistant cybersecurity worldwide.

Targeted markets:

N10gled targets cybersecurity for critical infrastructures, telecom, finance, and defence, delivering Quantum Keys as a service. Focused on commercial adoption, we begin in Europe, expand to North America and Asia, and scale to a global footprint.

Business model:

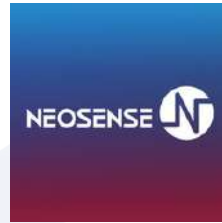
N10gled's core model is Quantum Keys as a Service, charging per key. Additional revenue comes from QKD subproducts (sources, detectors, photonic chips) and from ground stations and satellites, ensuring scalable growth.

Expected Collaboration:

N10gled seeks investors and partners to speed tech development- In pre-seed, we aim to raise 10M€ in 4 years to fund the development of ground stations, satellite IoT.

NEOSENSE

Category: Test & Instrumentation Equipment



Startup



France

www.neosense.tech

Our patented eddy current technology enables ultra-precise measurement of thin conductive layers, helping laboratories (R&D) and fabs (production) improve yield, reduce waste, and accelerate innovation.

Problem solved:

Measuring thin conductive layers is a challenge. Tools are often destructive, imprecise, or too slow. NeoSense offers a non-destructive, ultra-precise, and fast solution, improving quality, accelerating innovation, and reducing waste.

Differentiation:

NeoSense relies on 1 granted patent, 1 in preparation, and 3 proprietary know-hows from over 10 years of R&D.

Our deep expertise in eddy current physics and thin-layer measurement makes our solution unique and hard to replicate.

Unique Selling Proposition (USP) of your solution:

NeoSense offers semiconductor labs and fabs a unique ability to measure ultra-thin conductive layers non-destructively, even through insulators. This enables fewer defects, less waste, higher yield, and faster innovation cycles, directly reducing costs while accelerating time-to-market.

Solution description:

NeoSense has developed a non-destructive sensor that measures the conductivity of ultra-thin layers, even through insulating layers. This directly addresses key bottlenecks in R&D and production: material loss, yield issues, and slow development cycles.

Targeted markets:

NeoSense targets semiconductors in general, but currently focusing on the shift from Si to SiC & GaN. Highly insulating and defect-prone, these fast-growing materials are ideal for our non-destructive tech, also usable across R&D and manufacturing.

Business model:

NeoSense 1st generates revenues from hardware sales to labs and fabs, then builds recurring revenues through software, data services, and maintenance for industrial customers.

Expected Collaboration:

We are raising €4-6M in a Seed round. We seek collaboration to connect with investors and industrial customers, while challenging and refining our vision with expert feedback.

NORDAMPS AB

Category: RF&mmWave,[Other]



Startup



Sweden

<https://nordamps.com/>

NordAmps develops the next generation of nano wire transistor technology, combining unparalleled performance at high frequencies compared to existing technologies and highly scalable: Standing III-V nanowire transistors on Silicon. This technology breakthrough enables the next generation of RF components from 6 GHz to mmWave, forming the foundation for a broad portfolio (LNAs, PAs, Switches).

Problem solved:

While Moore's Law is slowing down for analog semiconductors and demand for data is exploding, a gap has emerged between market needs and what traditional technologies deliver. Alternative technologies offer performance but lack the scalability for the required volumes and cost.

Differentiation:

Our standing transistor technology uses minimal scarce materials while enabling excellent analog performance and scalable manufacturing. Combined with deep expertise and strong IP, this positions NordAmps uniquely to have exceptional growth in the semiconductor market.

Unique Selling Proposition (USP) of your solution:

NordAmps' standing transistor enables ultra-low-noise, power-efficient, and highly scalable for high-frequency solutions. Built on this breakthrough, our first products, high-performance LNAs above 6 GHz, help customers achieve superior performance and efficiency in their high-frequency applications.

Solution description:

NordAmps' standing transistor combines the scalability from traditional semiconductor technologies and the performance of alternative technologies, giving high performance in high volumes.

Targeted markets:

We target telecom infrastructure (5G/6G), satellite communications, automotive radar, and advanced sensing. Initial focus is on Europe and Asia, with global expansion as manufacturing scales.

Business model:

NeoSense 1st generates revenues from hardware sales to labs and fabs, then builds recurring revenues through software, data services, and maintenance for industrial customers.

Expected Collaboration:

NordAmps' standing transistor enables ultra-low-noise, power-efficient, and highly scalable for high-frequency solutions. Built on this breakthrough, our first products, high-performance LNAs above 6 GHz, help customers achieve superior performance and efficiency in their high-frequency applications.

ON NANO INTERNATIONAL GMBH

Category: Process Equipment & Manufacturing Tools



Startup



Germany

www.on-nano.com

At On Nano Int, GmbH, we combine groundbreaking technology with decades of expertise. Our mission is to provide customers with innovative, cost-effective, and environmentally friendly solutions with a very low CO2 footprint for the global chip and substrate market. We focus on advanced processes such as spin coating, developing, wet cleaning, etching, lift-off, and temporary bonding and debonding.

Problem solved:

Moore's Law nears its physical limits, shifting performance gains to advanced packaging. WLP faces key challenges in panel size and pitch scaling, which hinder efficiency and raise production costs—making further progress increasingly complex and expensive.

Differentiation:

On Nano holds key patents for coating, cleaning, and etching using a novel hot plate, boosting efficiency and reproducibility. We specialize in silicon, III/V materials, and glass—large (1,100 × 1,100 mm), small, concave, and convex. Thin glass wafer processes are also patent-protected.

Unique Selling Proposition (USP) of your solution:

NordAmps' standing transistor enables ultra-low-noise, power-efficient, and highly scalable for high-frequency solutions. Built on this breakthrough, our first products, high-performance LNAs above 6 GHz, help customers achieve superior performance and efficiency in their high-frequency applications.

Solution description:

Glass Panel Level Technology revolutionizes chip packaging, and ON-NANO leads the way. The company delivers cutting-edge machines & tools for wafers, substrates, and large glass panels. Unlike others, ON- NANO reliably processes panels up to 1.1 × 1.1 m—making it a true pioneer in next-gen panel-level packaging.

Targeted markets:

We target the global semicon market, focusing on adv. packaging and heterogeneous integration. Our customers include foundries, OEMs, OSATs, R&D labs, and integrators seeking innovative solutions for wafer, substrate, and glass panel processing.

Business model:

We generate revenue through direct sales of equipment and process solutions, supported by long-term service contracts. Active at key expos like SEMICON and Productronica, On Nano is a trusted innovation partner in packaging and glass panel technology

Expected Collaboration:

We are currently raising funds in a Series A round, aiming to secure €12 million to scale production, expand global operations, and accelerate technological development.

TIHIVE

Category: Mainstream Silicon Technologies, Packaging & Assembly, Test & Instrumentation Equipment



TIHIVE



Scaleup



France

www.tihive.com

Terahertz-on-Silicon sensing and vision solutions coupled with AI and big Data, for industrial and Space applications.

Problem solved:

Moore's Law nears its physical limits, shifting performance gains to advanced packaging. WLP faces key challenges in panel size and pitch scaling, which hinder efficiency and raise production costs—making further progress increasingly complex and expensive.

Differentiation:

We developed a full stack solution, from Terahertz chips, lenses, packaging, edge computing, AI algorithms & cloud. Our patented tech has been adopted by leading industrials. We are in commercial phase. Our solution offers the fastest processing and immediate analytics delivered to machines & humans

Unique Selling Proposition (USP) of your solution:

total qualification of production to increase yield, reduce waste and cogs, ensure quality

Solution description:

TiHive is the world's first to have developed, industrialised and commercialised See-Through Terahertz chipsets on Silicon (emitters and receivers) along with advanced optics, vision algorithms and AI, enabling 100% quality and process control in high speed.

Targeted markets:

high speed, volume industrial (textiles, plastics, composites, ceramics, polymers) high value industrial (semiconductors, luxury, space) Humidity monitoring (industry, agrofood, etc) medical sensing, 6G and space applications and prospective markets

Business model:

Inspection as a Service, where the hardware and software options are leased on a yearly basis

Expected Collaboration:

we have just raised 8M€ series A round and we are building for our next funding round (series B)

PULPOSEMI LTD

Category: PowerElectronics



Startup



Ireland

[PulpoSemi Ltd](#)

PulpoSemi Ltd is a fabless semiconductor company creating a revolutionary new genre of powering chips or voltage regulators (VRs) for AI chips, or more correctly for AI System-on-Chips (SoCs). PulpoSemi VRs will reduce the energy consumption of AI chips by 30% and solve thermal problems in data centers and enable AI chips at the edge deliver “energy constrained AI”.

Problem solved:

AI SoCs consume 1,000 Amperes today. In the next few generations the AI OEMs (Nvidia, Microsoft, AMD, IBM, etc) seek to get to 5,000 Ampers per AI Chip. PulpoSemi VRs enable this problem to be solved. PulpoSemi enables 50% energy reduction for energy-constrained edge AI.

Differentiation:

A very large body of licensed IP, patents from Tyndall, specially created for this startup. Only two tier-1 OEMs have similar levels of integration and PulpoSemi team members were involved in these developments in former roles. PulpoSemi has since created and licensed more advanced dedicated IP.

Unique Selling Proposition (USP) of your solution:

- 3 times the current density of any other known technology.
- This frees valuable interconnect real estate for HBMs (high bandwidth memories) under AI SoC – Lowest intrinsic electrical noise solution – Uniquely plan to offer optimised regulator per AI core.

Solution description:

Our solution uses miniature on-chip or in-substrate inductor components which operate at 100 times the frequency of today's solutions and enable 30 times size reduction by comparison with the voltage regulators on today's AI accelerator cards. This enables arrays of voltage regulators to be integrated in the AI SoC package and deliver optimal power to every individual AI core.

Targeted markets:

Tier 1 and Tier-2 AI System-on-Chip (AI SoC) OEMs for Data Center AI and “energy-constrained” Edge AI. Tier-1 (Nvidia, AMD, IBM, Amazon, Microsoft, etc. are US based). Edge-AI SoC companies are global. VRs for AI is a new emerging \$40B segment (2035)

Business model:

30% Revenues – Data Center AI SoC OEMs – an IP Business Model based around VR solutions
70% Revenues – Edge AI SoC OEMs – a fabless silicon model supplying fully integrated VR power system-on-chips (PwrSoC).

Expected Collaboration:

Our team is 6 years “in”. Thus far, zero investment. We seek €1-2M, 1st money but development-wise, are beyond “PreSeed”. Our full journey to alpha chips will require VC €6M, with €6M non-dilutive.

SCIPTech

Category: Packaging & Assembly



SCIPTech

Sustainable Chip Integration
& Packaging



Startup



Netherlands

www.SCIPTech.nl

Technology Development and Licensing of novel cost-competitive and environmentally friendly Advanced Packaging technologies.

Problem solved:

Over the decades, packaging manufacturing has migrated to Asia to benefit from the lower costs the region offers. This has left Europe with a severely diminished chip packaging capability. Also, Packaging (both classical and advanced) processes are highly polluting and energy-intensive industries

Differentiation:

Highly specialized in chip packaging technology and well-connected to the additive electronics ecosystem in the Netherlands. It is with this unique combination that such a ground-breaking idea was generated.

Unique Selling Proposition (USP) of your solution:

Half the packaging manufacturing cost, half the capital expenditure to setup manufacturing lines and significantly reduced environmental impact (still being quantified) and an economically viable solution to manufacture (chip packaging) in the western hemisphere and regain manufacturing sovereignty.

Solution description:

SCIPTech's new advanced packaging technology is based on an ADDITIVE process, which is low-cost and requiring low capital investment as well as being environmentally friendly. Packaging & Assembly costs in Europe, using this new technology, can be ~40% cheaper than products manufactured in Asia with current technologies.

Targeted markets:

Target market is very broad. Not targeting the very high-end packaging market with very high resolution needs (like AI chips), but the mid market, which makes up the majority of the chip packaging industry – from consumer products, automotive, etc.

Business model:

Attract material developers to co-fund the development activities with their materials, and when the solution is proven, offer TTLA Licenses to end users (IDM's with internal manufacturing or OSATs).

Expected Collaboration:

Idea needs more work to get a more robust proof of concept to attract industrial players to co-invest. A pre-seed funding stage of 1M EURO to cover the first 3 years of development work is needed.

SENTEA

Category: Test & Instrumentation Equipment, MEMS & Sensors, Photonics



SENTEA



Scaleup



Belgium

www.sentea.com

Compact and cost-effective read-out device for FBG fiber sensors

Problem solved:

– Fiber sensors are close to the ideal sensor: very sensitive, compact, light weight, and unaffected by EMI, extreme temperatures and. – But fiber sensor read-out devices (interrogators) are very expensive. – Sentea uses integrated photonics to make cost-effective interrogators

Differentiation:

- Exclusive licenses on key patents wrt silicon photonics from Imec/UGent in the field of sensing.
- Patents applications at interrogator system level
- World leading experts in the field of silicon photonics
- Our chips validated at 3 FABs
- Seasoned Management team

Unique Selling Proposition (USP) of your solution:

The cost of the interrogator is the main hurdle for large scale deployment of fiber sensors. Sentea's cost-effective interrogators make the business case work for continuous monitoring of critical assets to extend life time and increase efficiency.

Solution description:

Sentea developed an fiber sensor interrogator chip using a silicon photonics, making interrogators easy to manufacture and very cost-effective.

Targeted markets:

Wind turbines, high-voltage equipment (grid), industrial temperature and vibration sensors & automotive

Business model:

Sales of FBG sensing solution and service

Expected Collaboration:

Series A funding

POLAR LIGHT TECHNOLOGIES

Category: Photonics, Quantum Technologies



Scaleup



Sweden

www.polar-light-technologies.com

Polar Light Technologies AB develops microLED based in InGaN solutions.

Problem solved:

Current microLEDs are not able to do monolithic RGB. This makes it expensive to provide displays based on microLEDs.

Solution description:

We have a unique bottom up approach, which means that no etching is involved, which destroys the quantum wells. Furthermore, we grow our quantum wells on semi-polar plane and are able to do all three colors RGB.

Differentiation:

We have a very unique solution with pyramidal GaN structure and quantum wells on the semi-polar plane. No other commercial company does that.

Targeted markets:

Defense – Europe and USA XR and head up display – ASIA, Europe, USA

Unique Selling Proposition (USP) of your solution:

The USP is that we will be able to do monolithic RGB.

Business model:

We will sell display based on microLED

Expected Collaboration:

5 MUSD this is the nal round before Series A, we are very close to a product

NANOTECHNA S.R.O.

Category: Materials & Substrates, Power Electronics, Photonics



Startup



Czech Republic

www.nanotechna.cz

New generation chips – incorporation polymers in combination with nanoparticles into the current technical solution – procedure of making chip.

Problem solved:

Partly replacement of silicon in the current production chips for lower power consumption, lighter weight, and durability.

Solution description:

We are bringing new approach in procedure of making chip of a new generation, which brings exhibity stretchability, less power consumption. Incorporation of state-of-the-art approaches such as electrospinning and AM and usage on polymer membranes.

Differentiation:

New approach, using of photonic driven powering on polymer chip.

Targeted markets:

Power polymer chips cheaper, flexible and stretchable with low cost production and with biodegradable and biocompatible.

Unique Selling Proposition (USP) of your solution:

New technology, new generation of chips. Usage in Petahertz electronics two orders of magnitude higher frequency then current solution in a middle 5years and long term usage. 10years.

Business model:

B2B

Expected Collaboration:

TLR 3-4 laboratory verification Pre seed phase

IGNION SL

Category: RF & mmWave, AI/ML Hardware



Startup



Spain

<https://ignion.io/>

ignion is a pioneer in Virtual Antenna® technology, delivering multiband, multi-radio chip antennas that make RF integration predictable, faster, and future-proof. With more than 80 million antennas shipped, Ignion empowers developers to seamlessly integrate wireless connectivity. Our mission is to make RF effortless so creators can focus on building transformative solutions.

Problem solved:

IoT devices struggle with complex RF integration: antennas must be redesigned for each band or device, certification often fails on first pass, and efficiency drops on compact PCBs. These issues increase costs, delay launches, and slow IoT adoption.

Differentiation:

Ignion stands out with patented Virtual Antenna® IP, founders who are world-recognized RF inventors, and Oxion, the first AI-powered antenna design assistant. With over 80M units shipped and tier-1 validation, we combine unique know-how, protected tech, and proven scalability.

Unique Selling Proposition (USP) of your solution:

Ignion simplifies wireless design: one antenna, any band, any device. Customers cut 8–12 weeks off development, achieve 85–95% first-pass certification success, and eliminate supply chain complexity with a single SKU, while improving device efficiency and battery life.

Solution description:

Ignion's Virtual Antenna® is an ultra-compact chip supporting all major radios (LTE-M, NB-IoT, GNSS, Wi-Fi, BLE, 5G, LoRa) with up to 70% efficiency, even on small boards. Paired with Oxion, our AI platform, it delivers RF simulations, tuned BOMs, and validation in 48h—accelerating design, reducing failures, and making integration future-proof.

Targeted markets:

Ignion targets IoT gateways, industrial sensors, medical wearables, smart metering, utilities, asset tracking, and automotive telematics, with strong adoption in Europe, North America, and Asia.

Business model:

– Component sales of Virtual Antenna® chip antennas
– Oxion AI-powered antenna integration platform
– Engineering services (PoC simulation, tuning, pre-cert debugging)

Expected Collaboration:

Ignion is not currently seeking funding.

NSS WATER

Category: Materials&Substrates,ProcessEquipment&ManufacturingTools



Startup



Sweden

<https://www.nsswater.com>

NSS Water develops and commercialises patented Water Enhancement Technology (WET) to produce Nanopure® Water (NPW), the world's purest water. Our modular, point-of-use systems eliminate nano- contamination above 5 nm, improving semiconductor yields while reducing water and chemical use by up to 90%. We deliver sustainable, scalable solutions for fabs and other high-tech industries.

Problem solved:

Semiconductor fabs face two critical issues: nano-contamination in ultrapure water, where particles >5 nm cause costly yield losses, and extreme water use, up to 15M liters/day, straining resources in water- stressed regions. This drives high costs, waste, and environmental impact

Differentiation:

NSS Water's patented WET technology produces Nanopure® Water beyond UPW standards, eliminating particles >5 nm. Our modular point-of-use systems integrate at fab tools, cut water/chemical use by up to 90%, and recycle process water. Backed by 5 patents and deep semiconductor know-how

Unique Selling Proposition (USP) of your solution:

NSS Water delivers Nanopure® Water at the point of use, eliminating particles >5 nm that cause costly defects. This boosts yield in advanced nodes while cutting water and chemical use by up to 90%. Our patented WET technology lowers costs, enables recycling, and supports fab sustainability goals

Solution description:

NSSWater has developed WET technology, producing Nanopure® Water (NPW) that eliminates particles above 5 nm, the main source of chip- killing defects. Unlike today's large central UPW plants, our modular point-of-use systems deliver NPW directly at the tool, cutting water and chemical use by up to 90%, lowering costs, boosting yield, and enabling sustainable semiconductor manufacturing.

Targeted markets:

NSS Water focusing on front-end processes such as wafer cleaning, CMP, etching, and lithography where water purity is most critical. We address Europe (sustainability, EU Chips Act), Asia (Taiwan, Korea), and the USA (yield and water stress)

Business model:

NSSWater runs a B2B model, generating revenues from sales of WET systems (€250k- €2.5M depending on fab needs) and recurring service subscriptions. Add-ons for recycling and tool integration provide extra streams,

Expected Collaboration:

We are raising a €2M seed round to advance product development and pilot testing. We seek collaborations with fabs and OEMs

LOTUS MICROSYSTEMS APS

Category: Power Electronics



Startup



Denmark

<https://www.lotus-microsystem.s.com/>

Lotus Microsystems develops advanced power delivery and thermal management solutions for AI/HPC. As a fabless company, we design, test, and qualify products based on proprietary Power Interposer Technology (PIT) and advanced packaging, partnering with tier-1 fabs for production and serving leading AI/HPC customers.

Problem solved:

Given the increasing AI workloads and the unprecedented scaling rate of AI infrastructures, e.g. 1.7 TWh by 2030, power delivery technology for the AI GPU/CPU chips will become the key bottleneck to power efficiency.

Differentiation:

Our differentiation lies in 14 patent families and internal know-how, covering all aspects of power modules, from the substrate – the silicon Power Interposer, compact and efficient power ICs, and advanced packaging technologies.

Unique Selling Proposition (USP) of your solution:

Our solutions deliver up to 40% higher efficiency, 25°C cooler operation, and 70% smaller footprint. Superior electrical and thermal performance with heterogeneous integration, including backside power delivery. Fully compatible with the most advanced AI/HPC processors.

Solution description:

Our mission is to transform power and thermal management solutions to tackle the immense challenges of power delivery and unlock the full potential of AI and advanced process technologies for computing. Our modules cut footprint by 70%, lower temps by 25°C, reduce power loss up to 40%, and can support both the current and future AI chip architectures (e.g. backside power delivery).

Targeted markets:

We target three markets: 1) AI/HPC computing engines, 2) data connectivity, i.e. optical communication in data centers, and 3) thermal management solutions for advanced packaging and high-end processors.

Business model:

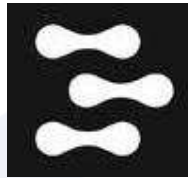
We design in-house and outsource to tier-1 fabs and OSATs. Revenues from custom solutions for strategic AI/HPC partners and ASSPs for broader markets. Products are sold via OEM direct sales and our worldwide distributor network.

Expected Collaboration:

We aim to raise €20–25M in Series A by end-2026 to scale US presence, industrialize PIT, execute product roadmap, and co-develop custom AI/HPC solutions with Tier-1 partners.

EXPECTED IT

Category: Mainstream Silicon Technologies



Startup



Germany

<https://www.expected-it.com/>

EXPECTED IT is a pioneering deep tech startup to disrupt the computer industry with our breakthrough server architecture for improving workload performance and costs within datacenters. The company was founded by a team with proven chip hardware expertise, commercial and entrepreneurial track records.

Problem solved:

Popular2-CPU servers efficiently integrate HW devices (CPUs, GPUs, memory,...). Its bottleneck is its small number of devices. Traditional 4+ CPU servers are a less efficient integration than 2-CPU servers. Data transfer across servers uses the network (Ethernet, IB), which is a bottleneck.

Differentiation:

Rack-scale server 32 CPUs and 0 to 64 GPUs. Server fabric spans the rack full-BW across a rack of devices. Endless configurations. Open to any PCIe-attached hardware. Off-the-shelf devices for low costs. 100% workload coverage.

Unique Selling Proposition (USP) of your solution:

Speed+Performance: up to 10x faster. Cost about 50%, Compatibility + Integration. Efficiency: 2x more cost-effective. Sustainability: reduce hardware usage by high compatibility with existing datacenter hardware and software, allowing for seamless integration and using devices from any vendor.

Solution description:

Based on our deep-tech breakthroughs in: – Memory coherence – PCIe tunnelling – Orthogonal-direct packaging with LPool, datacenters can build: – ultra fast (10x) – high efficiency rack-scale systems – in endless configurations – for 2x less cost – using off-the-shelf devices.

Targeted markets:

The target market consists of large players like Intel, AWS, and Microsoft (USA, Europe, Korea). The success with one major customer can lead to others following suit, creating a network effect that accelerates adoption.

Business model:

Licensing and Royalty Model: Our core revenue model is based on licensing IP and receiving royalties inherently.

Expected Collaboration:

Awarded: EIC Accelerator Horizon -> Series A: 10-12M EUR

SPIN ION TECHNOLOGIES

Category: AI/MLHardware



Startup



Germany

<https://www.spin-ion.com/>

At Spin Ion we develop on chip continual learning for edge AI chips.

Problem solved:

EdgeAI chips face 3 critical issues: latency, power consumption, most important edge AI chips can't learn once deployed. They need to be retrained in the cloud. This is a serious issue for security and data privacy.

Differentiation:

Using our unique ion beam process applied to the IMC device we fabricate for the first time metaplastic synapses with short and long term memory. Our technology is protected by a strong patent family and extensive know-how that creates significant barriers to competition.

Unique Selling Proposition (USP) of your solution:

We offer a unique solution with ultra low power and continual learning for edge AI chips.

Solution description:

We invented a novel hybrid In Memory Computing architecture where computation is performed directly in the memory, eliminating completely data transfer. Our solution results in 1000x improvement in energy efficiency but more importantly for the first time ever the ability to learn continuously on the device with no cloud connectivity

Targeted markets:

Realtime monitoring constrained edge devices Applications targeted : medical wearables & voice recognition & industry IoT.

Business model:

We position our selves as technology enablers, with an IP model process, software, and chip design.

Expected Collaboration:

We are aiming to raise 12,5M€ it will represent a pre-serie A.

SENSIFAI-EDGE

Category: AI/ML Hardware



Startup



Danemark

Not yet online

SensifAI-Edge develops neuromorphic AI hardware platforms for ultra-low power, high-performance edge processing. Our chips mimic the brain's information processing to deliver event-driven, real-time intelligence in power-constrained environments such as biomedical devices, wearables, robotics, drones, autonomous systems, and space applications.

Problem solved:

AI workloads are exploding, but cloud inference is slow, energy-hungry, and unsuitable for many edge applications (wearables, drones, implants, satellites). Edge devices need ultra-low latency, reliable, power-efficient AI, without it, adoption in critical markets is blocked.

Differentiation:

Unique chip architectures (NEXUS and SPIRE) with record-low energy per operation. On-chip learning with spiking neural networks, enabling adaptation. Patents on neuromorphic architecture design and edge-devices. Team recognized as leading a research group in neuromorphic computing.

Unique Selling Proposition (USP) of your solution:

Scalable neuromorphic chips that bring brain-like processing to devices at the edge:
1-Ultra-low power (orders of magnitude less than GPUs)
2-Adaptive learning
3-Scalability: one architecture, many applications. Reduce cost, extend battery life, and enable AI in places where today it is impossible

Solution description:

We design neuromorphic AI chips that embed brain-inspired neural networks directly at the circuit level, enabling real-time, on-device intelligence with a fraction of the power consumption of conventional accelerators, online learning and adaptive behavior, and a compact and scalable platform adaptable to multimodal inputs.

Targeted markets:

Biomedical devices (implantables, wearables). Robotics & drones (industrial automation, monitoring systems). Space applications (satellite onboard processing). Autonomous vehicles (edge perception). IoT & consumer wearables and many more

Business model:

Fabless chip design: sell chips via distributors
Licensing IP cores to semiconductor companies & OEMs. Custom ASIC services for high-value markets
Future: developer SDK & tools to support ecosystem adoption

Expected Collaboration:

€1M for 18 months to build our core team. This funding will enable us to move from the foundation phase to the evolution phase with NEXUS_V2 and SPIRE_V2.

WOOPTIX

Category: Test & Instrumentation Equipment, Process Equipment & Manufacturing Tools



Startup



Spain

www.wooptix.com

Building semiconductor metrology equipment for 3DNAND, LOGIC, D-RAM, etc. warpage Free-form wafer systems for global and local measurements in real time for fab environment.

Problem solved:

As semiconductor nodes advance into miniaturization (single-digit nanometer) we are providing the fastest and highest resolution metrology system for in-line processes in the fab.

Differentiation:

Highest resolution to measure the warpage of every wafer in-line even with a high warpage.

Unique Selling Proposition (USP) of your solution:

Highest resolution to measure the warpage of every wafer in-line even with a high war page.

Solution description:

Fab system for 3DNAND, LOGIC, D-RAM, etc. with a vertical holding of the wafer that enables to measure the warpage without gravity and process it in less than a second. This system enables chipmakers to qualify different processes as pre-post bonding, overlay, CMP and others.

Targeted markets:

3DNAND, LOGIC, D-RAM, IDM, Foundries. South/East Asia, Europe, US.

Business model:

Building Semiconductor equipment.

Expected Collaboration:

Series D to be closed on June 2026.

VTT / SOCOOL EIC PROGRAM

Category: Quantum Technologies



Startup



Finland

<https://soco ol- eic.eu/about/>

As of now, we are applying as the EIC program SoCool, but by the time of the event, we aim to already work on fundraising for the targeted spin-off / startup focusing on Solid-state Cooling for scalable cryogenics. The EIC program SoCool develops technology and commercialisation of the technology. Cryogenics is required for multiple growing segments – Quantum technologies, optical sensors, etc.

Problem solved:

Multiple cryogenic applications' performance and scalability are hampered by today's cryocooling technologies. We are positioned to change that and enable truly scalable cryogenics.

Differentiation:

Main expertise in the solid-state patents and technologies, difference comes from deep cooling knowhow based protection, as well as broad domain expertise of the team.

Unique Selling Proposition (USP) of your solution:

Unprecedented performance at a uniquely small form factor. Attractive price point for given performance and form factor.

Solution description:

Our solution is a system enabled by solid-state cooling for scalable cryogenics. Our solution unleashes unprecedented size and cost of cryocooling.

Targeted markets:

Europe, USA Quantum technologies, Optical sensors, RTOs, Fundamental physics.

Business model:

Product sales +SW and other lifetime services.

Expected Collaboration:

Seed, 2.5MEUR.

VOXELSENSORS

Category: Mainstream Silicon Technologies, MEMS & Sensors, Photonics



VoxelSensors



Startup



Belgium

<https://www.voxelsensors.com>

Our mission is to provide Perception-as-a-Service platform for the physical AI economy. We deliver an end-to-end solution combining ultra-low power sensing solutions with a powerful data platform, giving our partners all the tools they need to train and deploy intelligent robotics and AR/XR wearables in the real world.

Problem solved:

Cognitive robots, robots that use AI and vision to autonomously make human-like decisions, are the next big thing in robotics. Unlike language models, which train on massive internet datasets, robotics lack equivalent training data. We efficiently collect this data to learn task after task.

Differentiation:

We are uniquely positioned to deliver our vision as we control the technology stack from photon through sensors to data and action. This is a unique trait unavailable to most companies. In addition, our team has experience in scaling the tech stack and we are protected by 34 granted patent families.

Unique Selling Proposition (USP) of your solution:

We are building a full solution for egocentric data collection. By controlling the full stack from photon to action, we can capture just the relevant data when it matters. A better dataset results in higher accuracy predictions. With the platform, our customers can focus on their data needs.

Solution description:

We develop a full Perception-as-a-Service solution integrated in a wearable device for egocentric data capture at scale. The data captured and curacy generated will be used to build general-purpose robots with human-like capabilities, and wearables to enhance people's lives.

Targeted markets:

Robotics and wearable AR/XR devices in Europe, US and APAC For civil and defense use

Business model:

Our business models evolves over time: 1-2 years: deployment of sensors to create a foundational layer of data collection devices 3-4 years: + supervised data collection projects with industry partners 4+ years: + data curation at scale

Expected Collaboration:

We are raising our Series-A round of 15M€. Target closing before the end of the year.

VOCSENS

Category: Main stream Silicon Technologies ,MEMS&Sensors, Photonics



Startup



Belgium

<https://vocsens.com/>

VOCsSens, a Belgian deeptech, develops ultra-compact semiconductor multi-gas sensors to make air composition measurable and actionable. First applied to livestock ammonia monitoring for compliance, welfare, and efficiency, the platform also targets EV battery safety (thermal runaway), industrial sites, and smart buildings with early fire prevention.

Problem solved:

Many industries need accurate, affordable multi-gas sensors. Farmers must track NH_3 , CO_2 and CH_4 ; buildings require early gas detection; and EVs need battery runaway alerts. Current solutions are costly, bulky, or single-gas, and improvements are vital for safety and environmental protection.

Differentiation:

To the best of our knowledge, VOCsSens is the only company making semiconductor gas sensors based on multiple specific materials, protected by granted IP. This delivers accuracy, specificity, and cost efficiency. No other technology combines these, leaving competitors behind.

Unique Selling Proposition (USP) of your solution:

VOCsSens offers miniaturized multi-gas sensors combining accuracy, specificity, and cost efficiency. Customers reduce pain by replacing bulky, costly single-gas systems. They gain earlier detection, regulatory compliance, and improved safety and efficiency across farming, buildings, and automotive.

Solution description:

VOCsSens developed a miniaturized multi-gas sensor using a proprietary chemiresistive principle and standard semiconductor processes, making it cost-effective and scalable. A 16-material matrix enables reliable multi-gas detection. For buildings and automotive we supply the sensor for integration, while in farming we deliver QAirBarn, a full wireless device ready for barn deployment.

Targeted markets:

VOCsSens targets agriculture, smart buildings, and automotive markets worldwide. Our multi-gas sensors reduce emissions in farming, enable early fire detection in buildings, and improve battery safety in EVs paving the way for global deployment.

Business model:

VOCsSens runs a B2B model. We sell as components for integration in smart building and automotive markets. In agriculture, we provide full devices like QAirBarn with wireless connectivity for direct deployment.

Expected Collaboration:

We raise 5M€ to industrialize our sensors, scale production, and broaden the sensing portfolio, enabling fast market entry in agriculture, smart buildings, and automotive.

VERTICAL COMPUTE

Category: Main stream Silicon Technologies, Materials & Substrates, AI/ MLHardware



Startup



Belgium

www.verticalcompute.com

European deep tech semiconductor startup. Breaking the memory wall of AI chips by developing a Vertical Integrated Memory and Compute technology delivered as chiplets.

Problem solved:

The rapidrise of Generative AI is straining current memory technologies. SRAM is fast but lacks density, DRAM in HBM offers density but is expensive and power-hungry. This bottleneck drives up costs, energy use, and limits the scalability of advanced AI systems.

Differentiation:

Spin-off from IMEC. Raised 20M EUR pre-seed in Dec 24. Team of 25 people. Extreme fast execution (100 wafers already produced and tested) Disrupting magnetic vertical integrated memory. 17 patent applications led.

Unique Selling Proposition (USP) of your solution:

Ultra-high throughput w/ 3D chiplet contacts
Ultra-high density w/ 3D NAND coststructure Scalable + efficient w/ a tech roadmap Breakthrough shift w/ new application unlock (e.g. LLM on a chip)

Solution description:

By combining 3D-NAND manufacturing process and the best aspects of vertical domain wall memory and Spin-Orbit Torque (SOT) MRAM, Vertical Compute delivers SRAM-class speeds, above DRAM densities, and MRAM-grade endurance at a low cost.

Targeted markets:

Start with AI Inference consumer and cloud applications, expand to the entire Memory market. Worldwide. unlock new AI applications (business private AI assistant at the edge) and enable the post smartphone era (full LLM on a chip, in your hands)

Business model:

Sell 3D chiplets to the entire AI HW chip industry

Expected Collaboration:

20M EUR pre-seed in Dec 24.
Raising 30MEUR seed.

VIDEANTIS GMBH

Category: Mainstream Silicon Technologies, MEMS & Sensors, Photonics



Startup



Germany

www.videantis.com

videantis is a hidden champion in the processor architecture and advanced SoC domain. Our unique processor architecture combines AI and other processing types targeting high-efficiency embedded processing domains and is already successfully used in over 25M automotive cars date. Building upon our reputation in automotive, we now scale up the core to 5nm SoC level for deployment in various markets.

Problem solved:

Key problems in automotive and non-automotive semiconductor markets are high cost, high power consumption, low exibility and low utilization of existing solutions, and dependency on few dominating players from non- European world regions.

Differentiation:

Videantis has developed its proprietary core architecture in an evolutionary way for over 20 years, each generation being re ned through production use in various mar kets, resulting in unmatched efficiency, exibility, and the ability to handle all demanding key algorithms on one architecture.

Unique Selling Proposition (USP) of your solution:

Our USP is our unified processor architecture, integrating AI, imaging, computer vision, video coding, and signal processing on a single, scalable platform, delivering high efficiency, low power consumption, and small chip area while dramatically accelerating time-to-market with ease of programming.

Solution description:

Ou runique unified processor architecture executes AI, graphics, imaging, computer vision, video coding/decoding, and general signal processing on the very same hardware platform, resulting in high e ciency, high exibility, low cost SoC solutions.

Targeted markets:

Historically, videantis has focused primarily on the automotive market, being deployed in more than 25M cars. We are now expanding our scope towards the defense, security, wearables, robotics, drones, and industrial automation markets.

Business model:

Videantis generates revenue by licensing its processor IP, software, and development tools. With the 4th gen architecture, the business model is expanded towards custom SoCs, chiplets, and silicon-proven subsystems, targeting a 150x revenue growth.

Expected Collaboration:

We are currently raising a Series B round to complement a committed €12.5 million EIC Accelerator invest with target investment ticket sizes of €5-10 million for a total of €20 million on top of EIC.

TROPIC SQUARE

Category: Main stream Silicon Technologies, EDA&Design Automation, [Other]



Startup



Czech Republic

<https://tropicsquare.com>

Fabless semi vendor, focused on secure chips – pilot product T RO PIC01

Problem solved:

Replacing blackbox chips with auditable solution – long time missing. Kerckho's principles implemented at fundamental level of silicon. Root of trust and cryptographic identity.

Solution description:

TROPIC secure element chip – in volume production shipping to customers

Differentiation:

Different mindset – seeing open and auditable as a strength and fundamental principal to build secure systems.

Targeted markets:

Global market – EU, US, Asia

Business model:

Selling ASIC chip.

Unique Selling Proposition (USP) of your solution:

Security – no black box, no backdoor. Provably secure chip implementation Platform for building secure solution at embedded electronics level.

Expected Collaboration:

Series A, GTM and portfolio expansion.

TECHiFAB

Category: Mainstream Silicon Technologies, and Other

TECHiFAB



Startup



Germany

www.techifab.com

TECHFAB found the solution for the so far unsolved ever-increasing energy-versus-speed problem of computation: The training of AI models needs ever-increasing computation capabilities. New power stations are built next to the server farms to provide the energy needed for computation. TECHiFAB provides the TiF-technology to speed up computation while reducing energy consumption by >90%.

Problem solved:

Artificial Intelligence will be everywhere from the Edge to each and every server farm. The AI training takes time and is very costly, in computation and in energy. It is expected that training and computation may soon be limited by energy consumption. The answer to this problem is Analog Computing.

Differentiation:

The development of the TiF technology started back in 2011. The TiF technology relies on a very special material with very special properties which makes the TiF technology so unique. TECHiFAB was founded in 2021 and has created and owns several patent families, a number still growing.

Unique Selling Proposition (USP) of your solution:

TECHiFAB's USP is the very high computational speed, extremely reduced latency, combined with a massive reduction of energy consumption. TECHiFAB systems compute faster than quantum computers.

Solution description:

TECHiFAB has developed the TiF-technology to provide analog computing, smart architectures and new algorithms for Matrix-Matrix multiplication, AI training, Neuromorphic and Analog computing. TECHiFAB's TiF-technology is the answer to the problem neither NVIDIA nor Intel nor Google nor OpenAI is able to solve.

Targeted markets:

In the near future TECHiFAB will deliver small trainable AI chips enabling AI at the Edge, e.g. at each sensor. As arrays, crossbars and TiF chips grow bigger, computers and server farms are targeted. Every market. Worldwide.

Business model:

TECHiFAB will deliver chips, wafers and technology

Expected Collaboration:

With 16 M Euros committed TECHiFAB is looking for another 1.5 to 5,5 M Euros

SWEEPME! GMBH

Category: Test & Instrumentation Equipment, Process Equipment & Manufacturing Tools

SweepMe!



Startup



Germany

<https://sweep-me.net/>

SweepMe! develops universal test and measurement software that connects instruments from different manufacturers through an intuitive drag-and-drop interface. Engineers save time and costs by avoiding custom coding, accelerating R&D, and streamlining production testing. With 200+ supported devices and an open Python-based driver ecosystem, SweepMe! makes testing scalable and future-proof.

Problem solved:

Integrating instruments from different vendors is slow and costly, requiring custom coding for every setup. This creates inefficiency, high engineering costs, and delayed time-to-market. SweepMe! solves this with a universal, vendor-independent test platform.

Differentiation:

SweepMe! stands out as an AI-enhanced low code platform, with open Python-based driver architecture, reusable modules co-developed with users, and support for 250+ instruments. Unlike NI, Keysight, and others, we are truly cross-vendor, offering unmatched flexibility and sustainable test automation.

Unique Selling Proposition (USP) of your solution:

SweepMe! empowers users with no or less programming skills to automate complex measurement tasks quickly and intuitively through a drag&drop interface and allowing for AI-supported cross-vendor instrument control.

Solution description:

SweepMe! is universal test software that lets engineers connect and control instruments from any vendor via a drag-and-drop interface using AI support. Ready-made modules work like building bricks, shared and improved across users. This makes test setup faster, reduces costs, and ensures sustainable, reusable development from R&D to production.

Targeted markets:

We target semiconductor R&D and production testing, enabling multi-vendor instrument integration for wafer testing, device characterization, and process monitoring. We address the 30 billion USD test equipment market and the device manufacturers.

Business model:

Selling a SweepMe! Pro subscription (1200 € per year per computer setup) to enable advanced measurements as needed in industry. People can get started with a free simple version. Enterprise licenses with additional support for industry users.

Expected Collaboration:

We are looking for an investment of 1.2 Million € at mid to end 2026 being a pre-Series A for the scale-up of our subscription license business. We are looking for DeepTech/Tech/Software investors.

STEER LIGHT

Category: Photonics



Startup



France

www.steerlight.com

With its Silicon Photonics-based 1550 nm FMCW LiDAR, SteerLight is redefining the future of 3D perception

Problem solved:

The absence of compact, reliable, and affordable 3D sensing limits the mass adoption of autonomous systems in industry, infrastructure, and mobility. Solving this challenge is both a market opportunity and a societal need to boost safety, efficiency, and productivity.

Differentiation:

Our solution combines 9 patents and 3 pending applications in silicon photonics, lens-free optical beam steering, and system design with expert 1550 nm FMCW laser control, enabling precise, high-performance LiDAR operation and strong market differentiation.

Unique Selling Proposition (USP) of your solution:

Our competitive edge lies in its compact, scalable architecture and solid-state design eliminating moving parts for enhanced reliability. It offers high-resolution, precise detection even in harsh conditions and cost-effective production using established silicon foundries' photonics processes.

Solution description:

SteerLight is positioned to pioneer the first fully solid-state FMCW LiDAR by integrating mechanical- and lens-free beam steering with range and velocity detection at the chip level. This enables optical engines 20x smaller, 10x lighter, and under €100/unit at scale, accessing markets unreachable by bulkier lens-based systems.

Targeted markets:

SteerLight's LiDAR solutions target four main markets: robotics, smart infrastructure, robotic cars, and autonomous vehicles. These segments represent a Total Addressable Market (TAM) of approximately \$7.5 billion by 2032.

Business model:

Our business model focuses on co-development with Tier-1 suppliers and robotics OEMs, alongside selling evaluation kits and COTS to logistics and infrastructure clients, generating revenue through licensing, NRE contracts, and component sales.

Expected Collaboration:

After our pre-seed round in Q1 2024, we plan to raise €8 million in equity in a seed round by Q1 2026,

SPINNCLLOUD

Category: Mainstream Silicon Technologies, AI/ML Hardware, [Other]

SpiNNcloud



Startup



Germany

<https://spinncloud.com/>

SpiNNcloud offers brain-inspired supercomputing technology for complex, AI-driven systems. The SpiNNaker2 architecture supports dynamic sparsity in mainstream AI applications with superior energy efficiency.

Problem solved:

Energy consumption has emerged as a key limiting factor for datacenter growth & sustainability. Hardware algorithms Mismatch. AI systems struggle with reliability in real-world applications, failing when processing data that differs from their training sets or when involves non-deductive reasoning.

Differentiation:

70,000+ chips produced (proven technology and validated supply chain) 40% PhD rate in relevant fields of research €10M revenue expected in 2025 (market validation from top institutions in the EU & US) Built the world's largest brain-inspired supercomputer (proven scalability and performance)

Unique Selling Proposition (USP) of your solution:

SpiNNcloud delivers ultra-efficient, low-latency inference for large AI models. Our event-driven architecture reduces power consumption and costs, addressing energy bottlenecks and boosting performance for deployments and research.

Solution description:

SpiNNcloud has developed a revolutionary brain-inspired computing architecture purpose-built for dynamically sparse inference – delivering up to 78× energy savings for AI inference. Through its high-speed and massive energy efficiency, we can both tackle the problems of energy consumption and scalability as well as the lack of power.

Targeted markets:

SpiNNcloud targets AI inference in cloud and enterprise data centers, mainly in North America and Europe, serving hyperscalers and large enterprises with efficient, sparse, real-time model execution, capturing \$100B+ SAM by 2030.

Business model:

SpiNNcloud generates revenues by selling specialized AI inference hardware and systems to research institutes, offering direct sales, integration services, and long-term support contracts for high-performance deployments.

Expected Collaboration:

We are looking forward to connect with investors, focussing on our Series-A Funding Round. We're aiming to raise approximately \$30Mio..

SONAIR AS

Category: MEMS & Sensors

+ Sonair



Startup



Norway

www.sonair.com

Sonair develops ADAR, the world's first safe 3D ultrasonic sensor for robots. It gives robots omnidirectional depth perception at half the cost of LiDAR, unlocking scalable safety and autonomy across industrial and mobile applications.

Problem solved:

Autonomous robots need reliable 3D sensing to operate near humans, but current solutions are bulky, expensive, and 2D-limited. Sensors can make up 30% of robot cost, slowing adoption in safety-critical, human-centric environments.

Differentiation:

Sonair's key differentiators are its patented 3D ultrasonic sensing technology, proprietary signal-processing algorithms adapted from medical ultrasound, and a proven deep-tech team.

Unique Selling Proposition (USP) of your solution:

ADAR simplifies safety compliance, reduces false stops, and lowers system costs. By enabling reliable human and obstacle detection, ADAR unlocks safe automation in environments where traditional sensors fall short.

Solution description:

ADAR is a compact, safe 3D ultrasonic sensor that detects humans and obstacles in all directions up to 5m. Powered by patented MEMS hardware and ultrasound algorithms, it enables robots to see in 3D—safely, affordably, and at scale.

Targeted markets:

Initial focus is on Automated Mobile Robots (AMRs) and machine safety. Key markets are the EU, US, and Japan, where automation is mature and growing rapidly.

Business model:

Revenue comes from direct product sales to OEMs, who integrate the ADAR sensor into their robots and machines as part of their commercial offerings.

Expected Collaboration:

Sonair is preparing a €10M Series A to scale production and commercial rollout. We seek deeptech investors and strategic partners through the CHIPS program and Venture Forum.

SISUSEMI OY

Category: Process Equipment & Manufacturing Tools



Startup



Finland

www.sisusemi.com

SisuSemi transforms the way, how to address atomic-level impurities at semiconductor interfaces, improving chip performance and optimizing production efficiency. The solution uses Ultra High Vacuum, elevated temperature ($< 450\text{ }^{\circ}\text{C}$) and controlled oxidation to clean silicon surfaces, restore crystalline structure and form a very thin crystalline SiO_2 layer to protect the silicon surface.

Problem solved:

Atomic-level defects and contamination have been an overlooked issue. They significantly drive down semiconductor performance and reliability. Impurity-triggered leakage currents also increase power consumption. In addition, 70% of manufacturing yield loss can be attributed to defect density.

Differentiation:

Our method and technology is protected with 4 patent families in key markets of Europe, N-America, Asia and China. 1 more patent is already applied. The key inventors of the IPR are in the founding team, complemented with experienced leadership, commercialization and sales professionals

Unique Selling Proposition (USP) of your solution:

SisuSemi creates impact at 3 levels:

- Directly: Improves wafer surface quality and chip performance,- In synergy: Enhances downstream processes like deposition, etching, and lithography
- Unlocking: Allows full utilization and corrections for quality issues that are detected with AI/ML models

Solution description:

Our solution uses Ultra High Vacuum, elevated temperature ($< 450\text{ }^{\circ}\text{C}$) and controlled oxidation to clean silicon surface, restore crystalline structure to and form a very thin crystalline SiO_2 layer to protect the silicon surface and enhance further processing. Results: Up to 25% lower power consumption and up to 20% higher manufacturing yield, enhanced chip speed, sensitivity and reliability.

Targeted markets:

We are targeting atomic-level cleaning markets of semiconductor manufacturing. Our target markets are IDMs and foundries in Europe, Asian markets, the USA and China. Furthermore, indirectly we are targeting also other SMES and Fabless co's.

Business model:

Primary revenues come from commercial implementation of the solution in the customer fabrication line and related continuous support fees. In addition, revenues from feasibility testing and commercial piloting, paving way for full implementation.

Expected Collaboration:

We are now looking for seed funding amounting 2,5 M€.

SIPEARL SAS

Category: Mainstream Silicon Technologies



SIPEARL



Startup



France

<https://sipearl.com>

Sipearl is developing a high performance energy efficient processors for HPC, AI and Datacenters

Problem solved:

Address strategic dual-use challenges in the elds of security, defence, health, energy and engineering with a reduced environmental footprint

Solution description:

Sipearl has built an european team capable to developp a CPU. Sipearl uses datacenter 100% based in France

Differentiation:

ARM based solution

Targeted markets:

Datacenters Computer / AI / Hign Performance

Business model:

ND

Unique Selling Proposition (USOP) of your solution:

ND

Expected Collaboration:

Sipearl closed a serie A amounting to 132m€. Sipearl is launching a B series of 220m€ is several tranches

ANNEX- B- Satisfaction Survey



Participants' experience of the 2025 CVF



- The Chips Venture Forum survey was conducted to assess participants' experience of the 2025 edition and to better understand expectations for future.
- A total of 39 respondents completed the questionnaire, representing a balanced mix of Investors & Corporates, Innovative Companies and Institutions/Competence Centers.
- Responses were collected between November 24 and December 22, 2025, just after the event ensuring fresh and experience-based feedback.
- The survey covered all key touchpoints
 - overall satisfaction,
 - application process,
 - digital jury, program & content,
 - networking, one-on-one meetings,
 - logistics,
 - deal expectations.

Chips Venture Forum

Please note: the form must be completed step by step without going back unless required fields are filled, we recommend completing it in one go. You'll be able to review and edit your answers after submission.

First/Last name*

First

Last

Business Email address*

Organization name*

Are you?

Please select

What is your general point of view on the Chips Venture Forum?

Please rate your overall impression of the Chips Venture Forum using the scale below, where 0 means 'Not good' and 10 means 'Very good.'

0

1

2

3

4

5

6

7

8

9

10

0

1

2

3

4

5

6

7

8

9

10

About the preparation of the Chips Venture Forum*

Not good

Average

Good

Very Good

Not applicable

How would you rate the application process?

How would you rate the digital jury phase?

Did you find the Webinars helpful to prepare your participation to the CVF ?

About the Chips Venture Forum Day*

Not good

Average

Good

Very Good

Not applicable

How did you assess the quality of the event organization?

How do you assess the Program Content of the day?

How do you assess the production of start-ups?

How do you assess the quality of the pitches of start-ups?

How do you assess the Quality of Moderation ?

How would you rate the one-on-one meetings?

About the Venue*

Not good

Average

Good

Very Good

How was the logistics for you?

How do you assess the Premises / Environment of the event?

How was the catering?

Did you enjoy the welcoming cocktail?

Did you enjoy the networking time?

With whom did you build valuable new connections?

Choose 1 to 3 organizations in the categories below. You can add more by clicking 'Add another connection'

Corporates & Investor partners

Innovative companies

Institutions

Please select

Please select

Please...

Add more connections

Please specify the entity name if it's not in the dropdown list

Do you expect any concrete deal opportunities in the next months with at least one of these organizations?

Yes

No

Tell us more about your expectation of deal opportunities

How do you assess the interest of the Chips Venture Forum for your organisation?

Please select

Why?

What are the key highlights of the Chips Venture Forum for you?

What should be improved?

Would you consider your participation to the 2025 edition of the Chips Venture Forum ?

Would you recommend the Chips Venture Forum to your peers?

Funded by the European Union

25/02/2026

Europe Chips JU under Grant Agreement No 101217840.

aCCcess has received funding from the European Union's Digital



CVF: main feedback



- **High satisfaction and loyalty:** most participants rate the forum 8/10 or above, and more than 92% intend to return for the 2026 edition.
- **Real business acceleration:** the forum generated 112 new connections that are already evolving into qualified opportunities and future deal pipelines.
- **High-value interactions:** participants particularly appreciated the quality of moderation, relevance of content, event organization, and networking opportunities.
- **Investor efficiency:** investors highlight CVF as an effective deal-sourcing and screening platform, helping them focus on companies aligned with their investment scope.
- **Startup benefits:** innovative companies value visibility, strategic learning, and direct access to key investors and partners.
- **Ecosystem alignment:** by bringing together innovators, corporates, investors and institutions, the forum strengthens collaboration around European industrial sovereignty and the ambitions of the EU Chips Act.

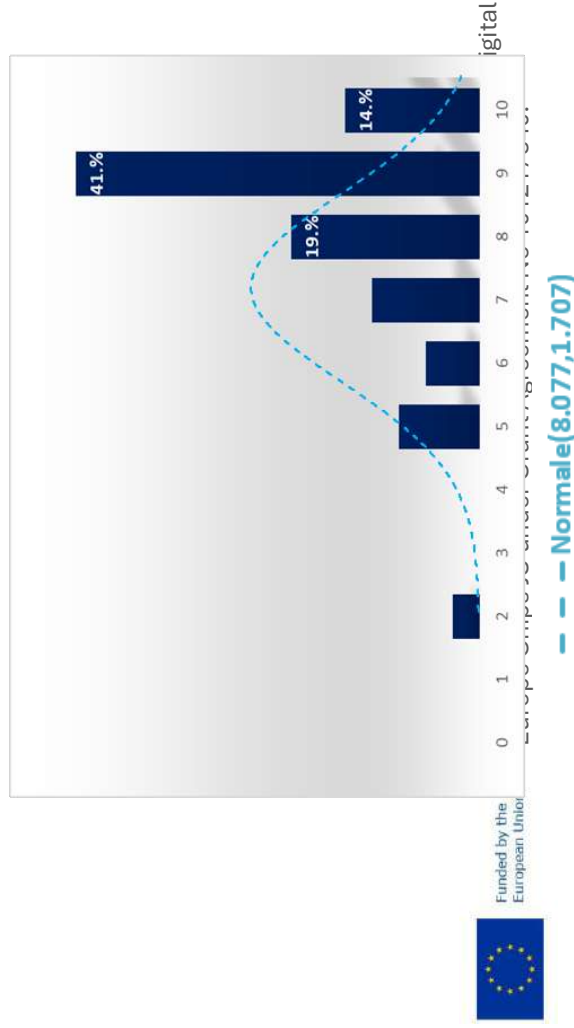


Over 70 % of respondents rated the event 8/10

Satisfaction Score Strongly Concentrated at a High Level



- More than 70 % of respondents rated the event 8/10 or above reflecting a widely shared perception of a high-quality.
- The normal curve represents a smooth reference distribution estimated from the overall score data, centered on an average score of 8.077 showing that scores are concentrated around eight out of ten and that most participants awarded high ratings.



Focus Investors & Corporates

- At least three quarters of investors and corporates rated the CVF at 8 out of ten or higher, confirming an exceptionally strong satisfaction.
- Investors & Corporates tend to give higher scores when the forum aligns well with their investment scope or CVC mission.

Focus : Innovative Companies & Competence Centers

- Half of innovative companies and competence centers gave the event a score of 9 out of ten or higher, showing a very strong overall level of satisfaction.
- Innovative Companies & Competence Centers are more sensitive to visibility (pitches) and the quality of networking interactions, which strongly influence their final score.

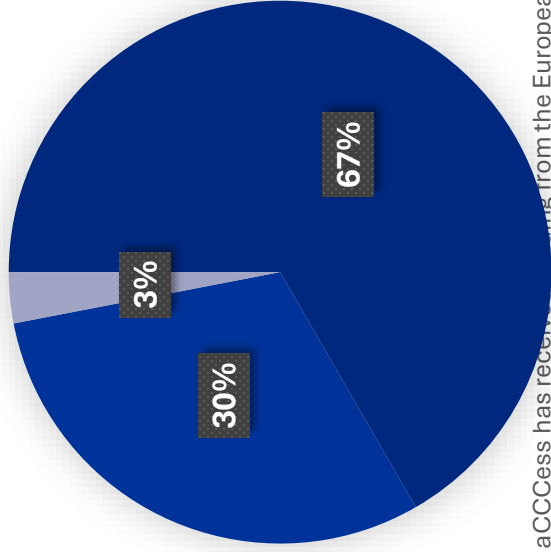


97% rate the application process positively, enabling a smooth start

How would you rate the application process?

The application process is very strongly rated, with 67% “Very Good” and 97% positive ratings overall.

It performs at a level comparable to core content questions, confirming a smooth and reassuring entry point into the program.



aCCcess has received funding from the European Union's Digital Europe Chips JU under Grant Agreement No 101217840.

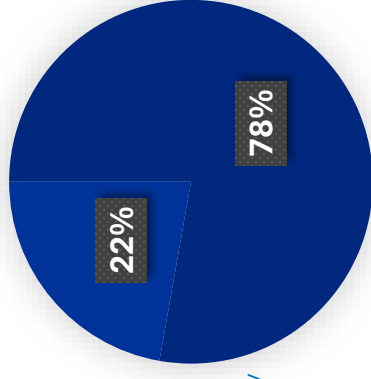
■ Very Good ■ Good ■ Average



Funded by the
European Union

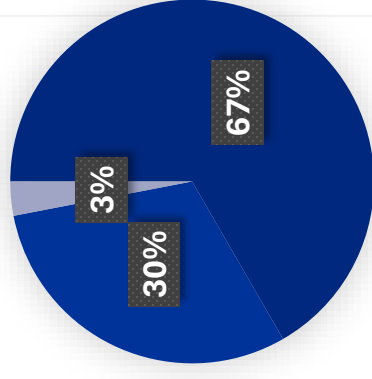
Focus Investors & Corporates

They show the highest level of satisfaction with 78% rating the application process “Very Good”. Feedback points to a process seen as efficient and well aligned with investor expectations, supporting deal sourcing and screening objectives. They underline that it is “a *very efficient way to identify opportunities in Europe*”.



Focus : Innovative Companies & Competence Centers

Positive feedback highlights clarity and ease of participation, with respondents noting “a *very good and easy-to-follow format*” and “an *overall favorable impression*”. The few more moderate ratings mainly reflect expectations for clearer selection criteria.

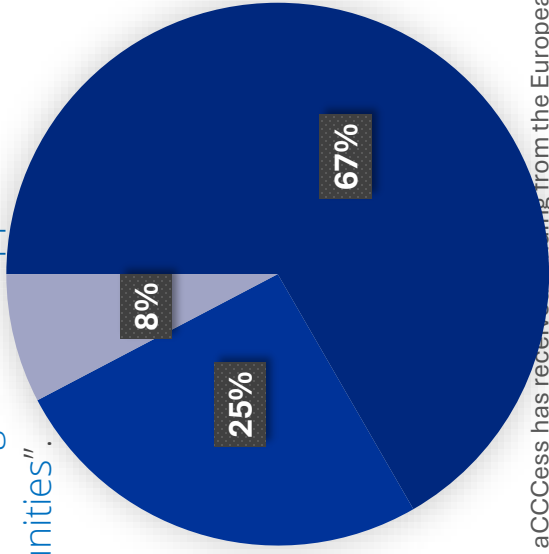




A high-impact program with 92% positive ratings

How do you assess the Program & Content of the day?

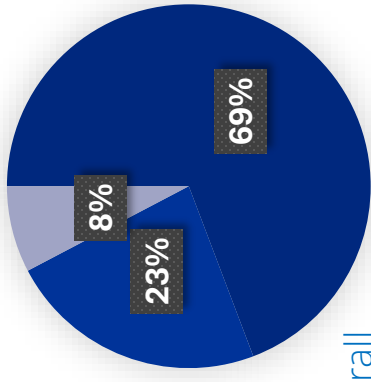
Program and content score very high and stable, with 67% “Very Good” and 92% positive feedback. Feedback highlights the clarity of the agenda, its alignment with semiconductor ecosystem challenges and the value of combining policy, investors and start-ups, as reflected in comments such as “understanding investor appetites for semiconductor opportunities”.



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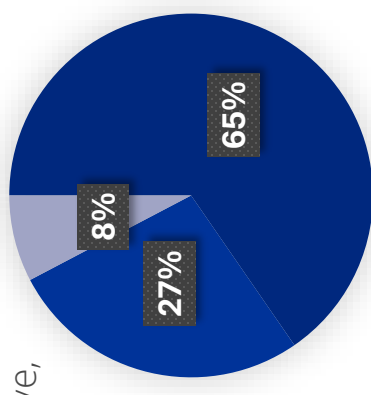
Focus Investors & Corporates

They value the Program & Content as efficient, well-structured and directly relevant to investment and strategic objectives. Verbatims underline “The whole program was great”, “strong interest in the technology area”, a “good cross-section of technologies that are relevant” and a “the pitches, the interaction, overall very pleasant to be among the right audience with the same focus”



Focus : Innovative Companies & Competence Centers

They particularly value the ecosystem-wide perspective, investor panels, and market clarity, citing “good combination of expertise and money at the same event” and “helped us better understand the ecosystem”. The event “provide a chance to scope for potential collaborations on targeted competence for the corporate.”



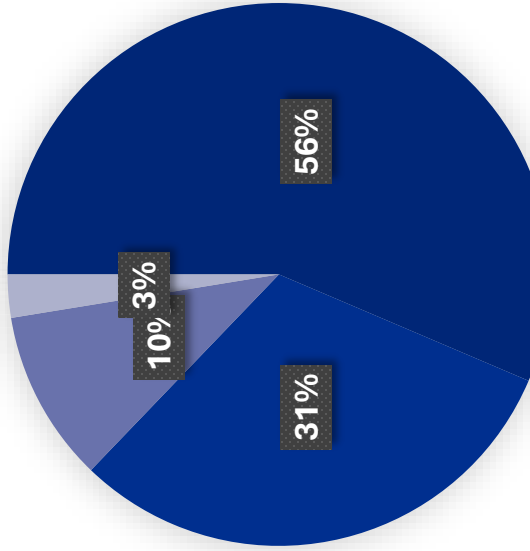


High-quality startup pitches, recognized by 87% of participants

How do you assess the quality of the pitches of start-ups?

Pitch quality receives 56% “Very Good” and 87% positive ratings, placing it slightly below start-up selection and clearly below moderation.

This suggests good overall quality but perhaps with a room for further sharpening.

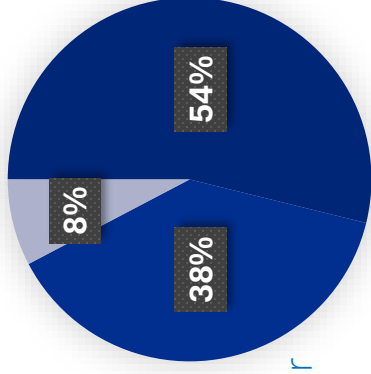


aCCcess has received funding from the European Union’s Digital Europe Chips JU under Grant Agreement No 101217840.

Focus Investors & Corporates

This group emphasizes the pitches as an efficient filtering and screening tool, allowing them to quickly assess technological relevance and strategic fit.

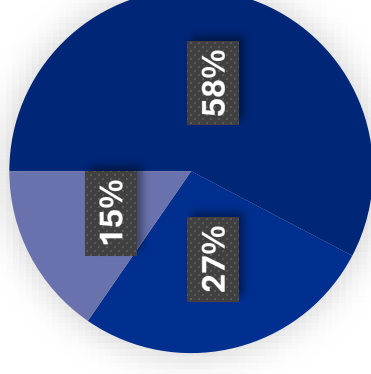
Feedback frequently refers to “high quality pitches”, “High quality startup pitch event with direct relevance for our mission.” and “Great presentations [...] Some insightful questions asked by some audience members”



Focus : Innovative Companies & Competence Centers

Respondents value the pitches as a visibility and learning opportunity, helping them benchmark their positioning and understand investor expectations.

Verbatims highlight the value of “being invited by investors to send a pitch deck”, “good quality presentations” and “relevant selection of startups.”



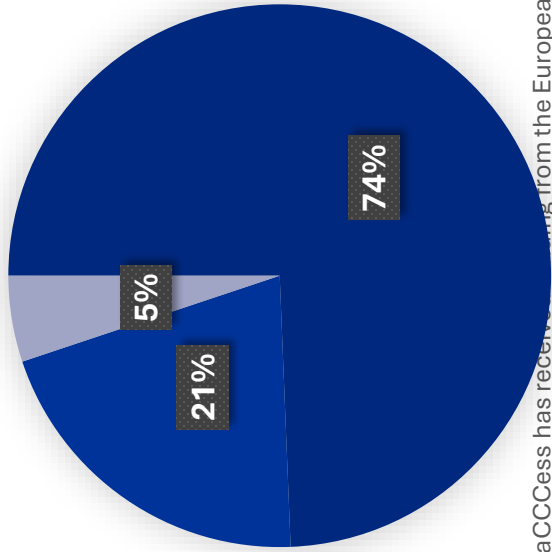


Moderation stands out as the #1 strength with 95% positive ratings

How do you assess the Quality of Moderation?

Moderation stands out as the highest-rated dimension overall, with 74% “Very Good” and 95% positive ratings.

It outperforms all other questions, underlining its critical role in structuring and energizing the event.



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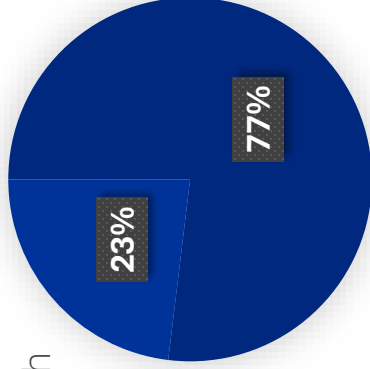
■ Very Good ■ Good ■ Average



Funded by the
European Union

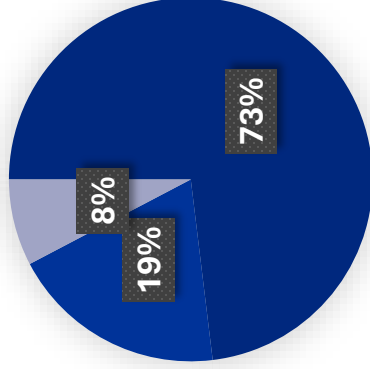
Focus Investors & Corporates

Moderation receives unanimously positive feedback, with 77% rating it “Very Good” and 23% “Good”, and 0% “Average”. This group values moderation for keeping discussions focused, relevant and efficient, particularly during panels and pitches. “The pitches, the interaction, overall, very pleasant to be among the right audience.”



Focus : Innovative Companies & Competence Centers

Positive feedback highlights moderation as clear and helpful in understanding investor perspectives, with comments pointing to the value of panels and structured exchanges.



Some respondents nevertheless express a desire for more moderation to “involve the audience more” in certain sessions.